



WORKSHOP OF PHOTONICS

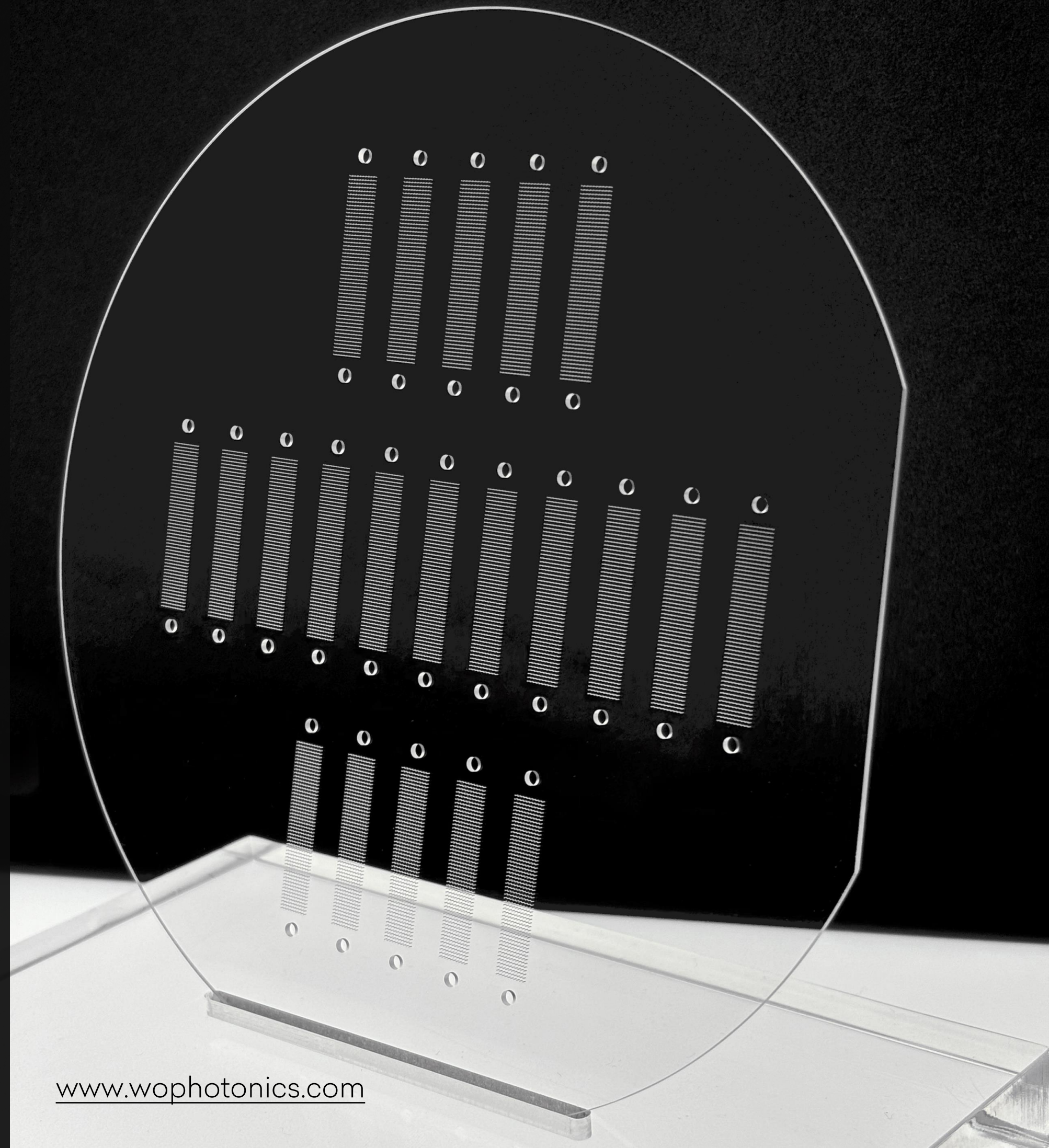
Advanced SLE Techniques for Enhanced 2D Optical Fiber Alignment in Dense Data Transmission

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Technical Project Manager

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We deliver **solutions** for **your μ tasks**



20 years of expertise

in femtosecond laser micromachining
with a high focus on glass



Patent family of 13 in-house and 2 licensed patents



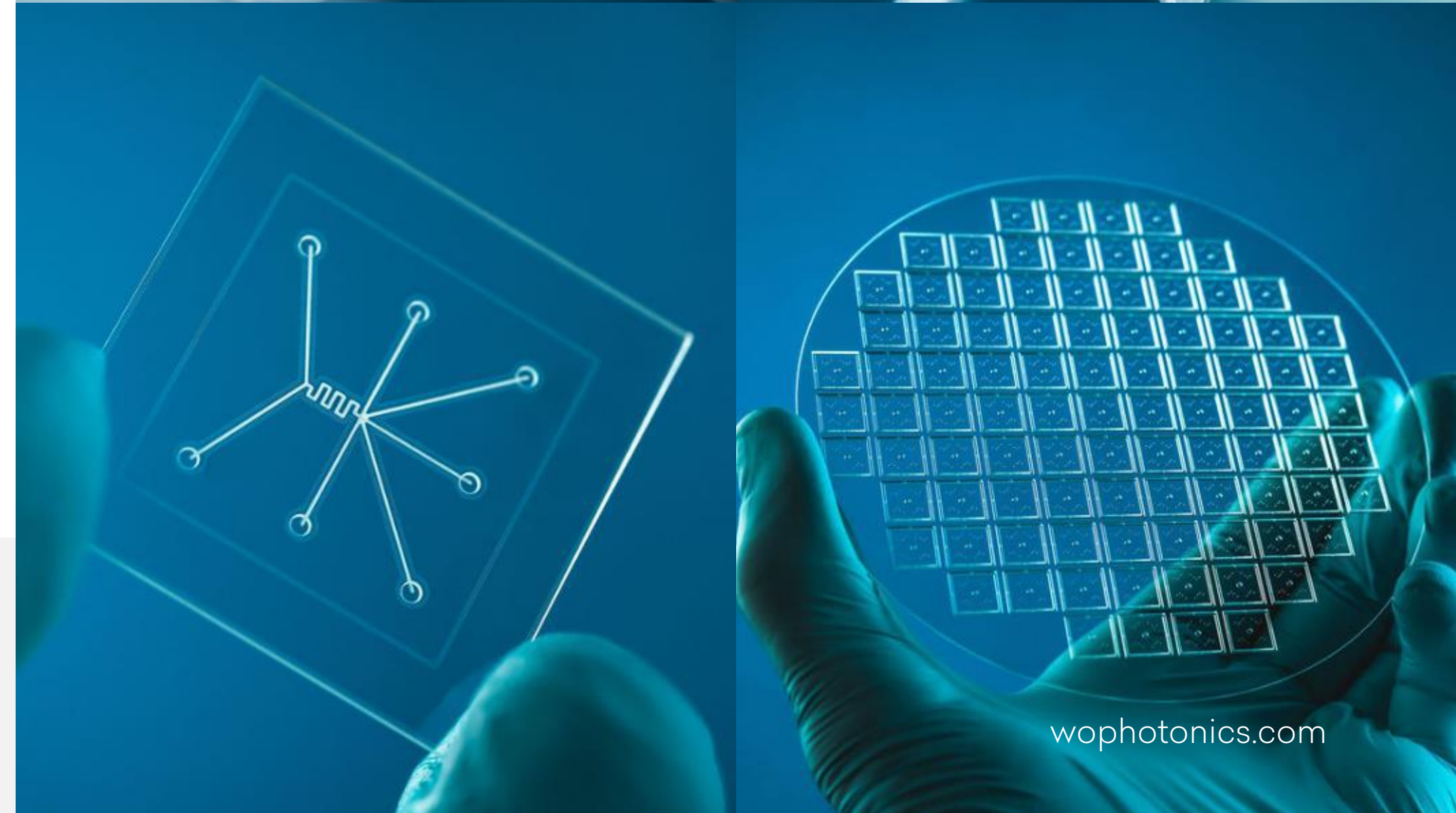
50+ professionals

7 Ph.D., 45 M.S. and B.S.



R&D studies

continuous projects with academic
and research partners



Members of



ISO certified



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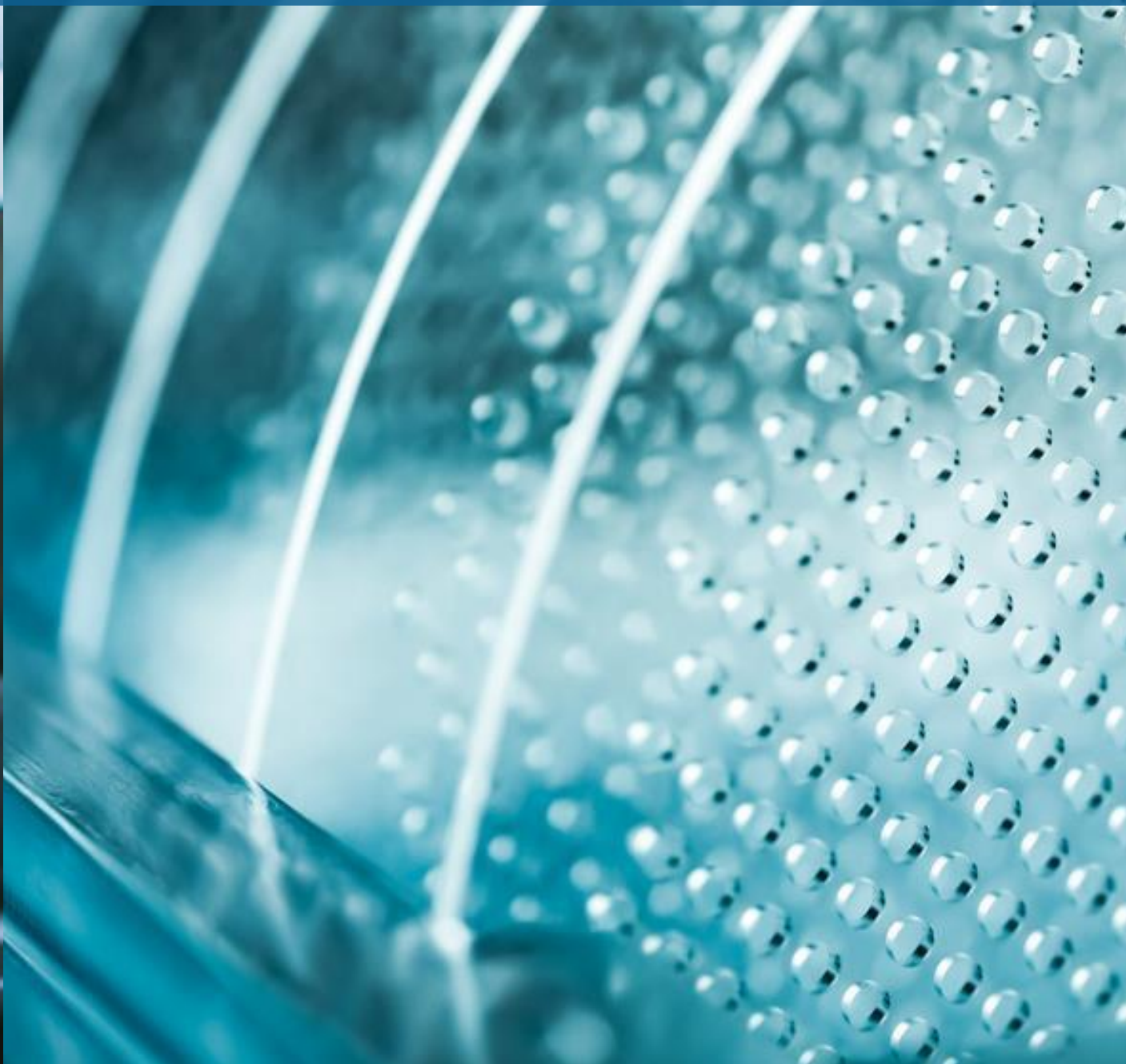
Solution
development | R&D



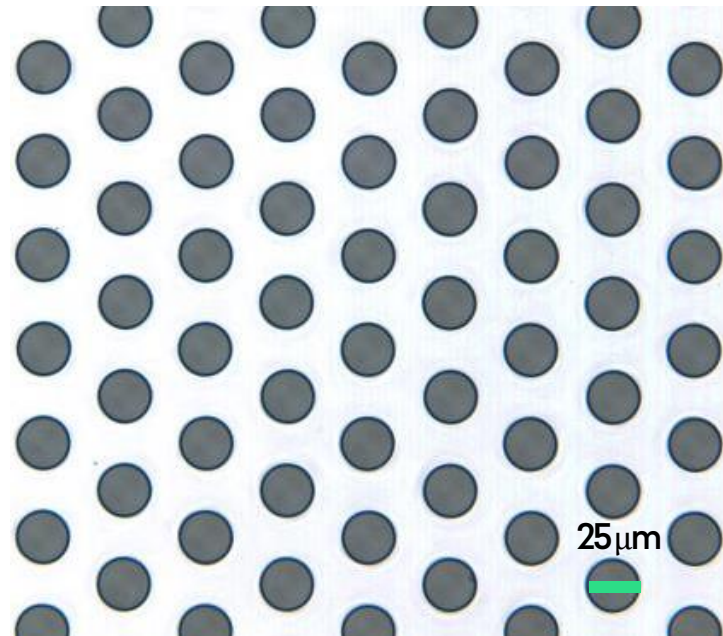
Contract
manufacturing



Hardware |
laser systems



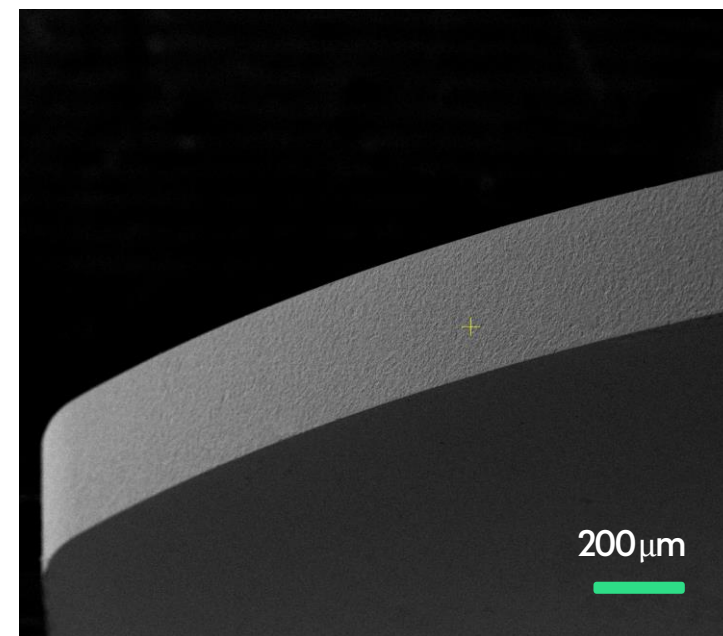
WOP Laser Applications



LASER MICRO DRILLING

Glass, Sapphire, Silicon, Ceramics,
Optical Fibers, Metal, Plastic

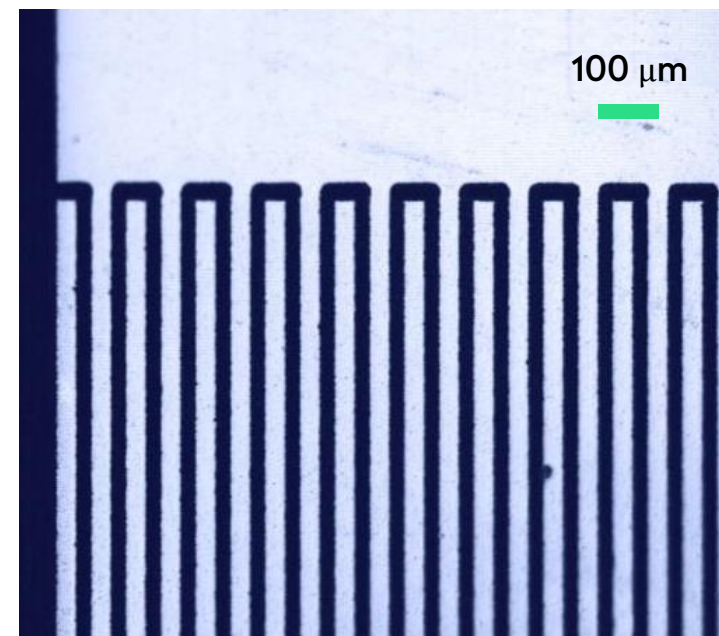
Picture: glass wafer drilling



LASER MICRO CUTTING

Glass, Thin Films, Foil, Sapphire, Polymers

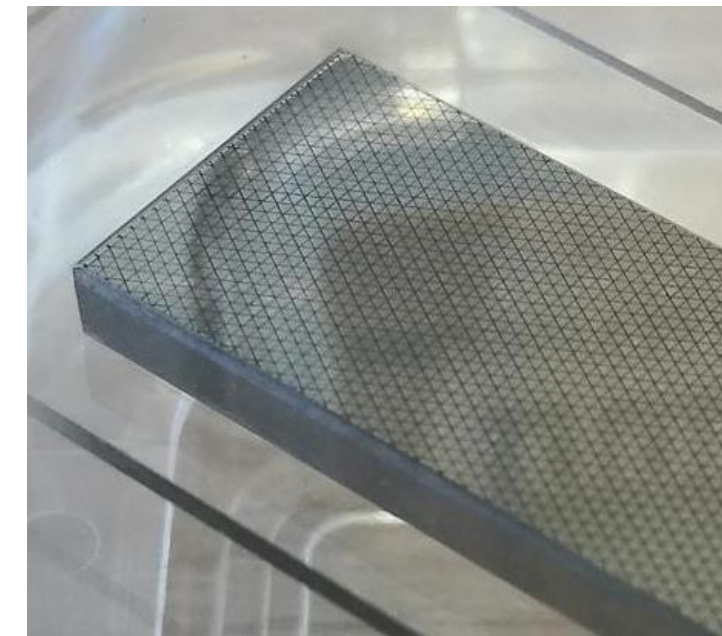
Picture: D263T glass cutting, thickn. 300 μm



SURFACE STRUCTURING

Selective laser ablation
Functional surface modification
Fiber tip processing

Picture: chrome ablation from glass substrate



LASER WELDING

Transparent materials with transparent
and non-transparent materials

Picture: glass to metal welding



SELECTIVE LASER ETCHING | SLE

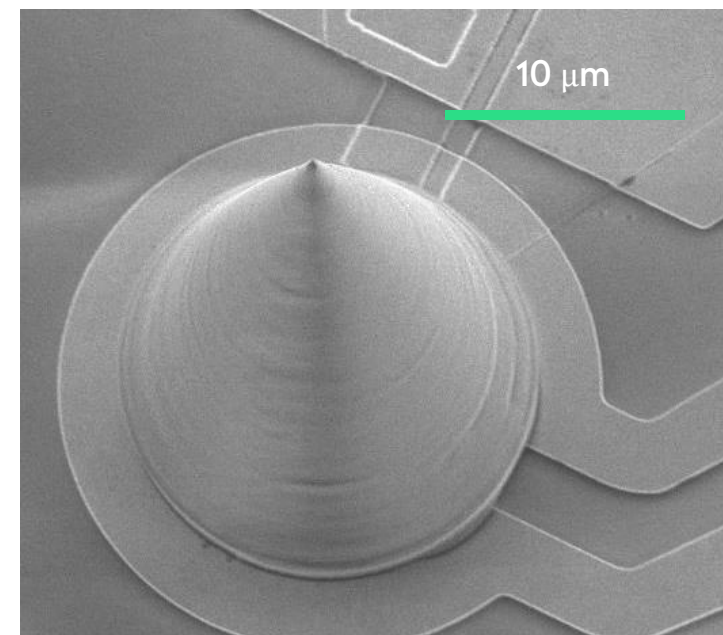
Picture: fiber alignment arrays, with SLE



LASER MICRO MARKING

Inside transparent materials
On the surface of various materials

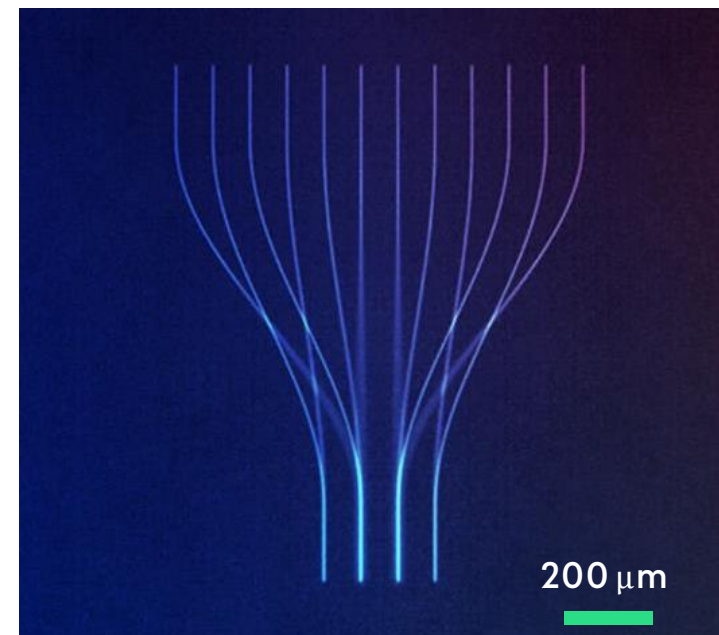
Picture: written directly inside the object by making refractive index irregularities without damaging the surface.



MULTIPHOTON POLYMERIZATION

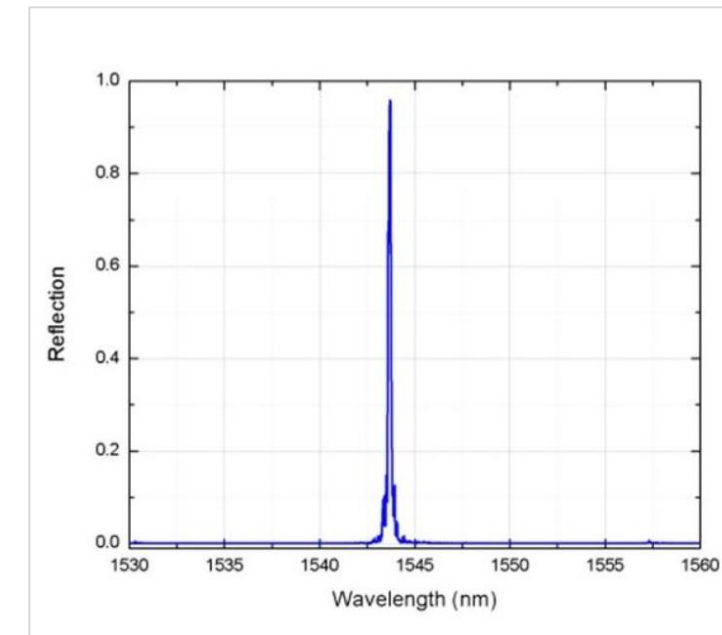
MPP, 2PP

Picture: functional structures nano printing on existing functional devices



WAVEGUIDE WRITING

2D & 3D waveguide writing



FBG WRITING

High reflectivity and transmission FBG's

SLE is a two-step process:

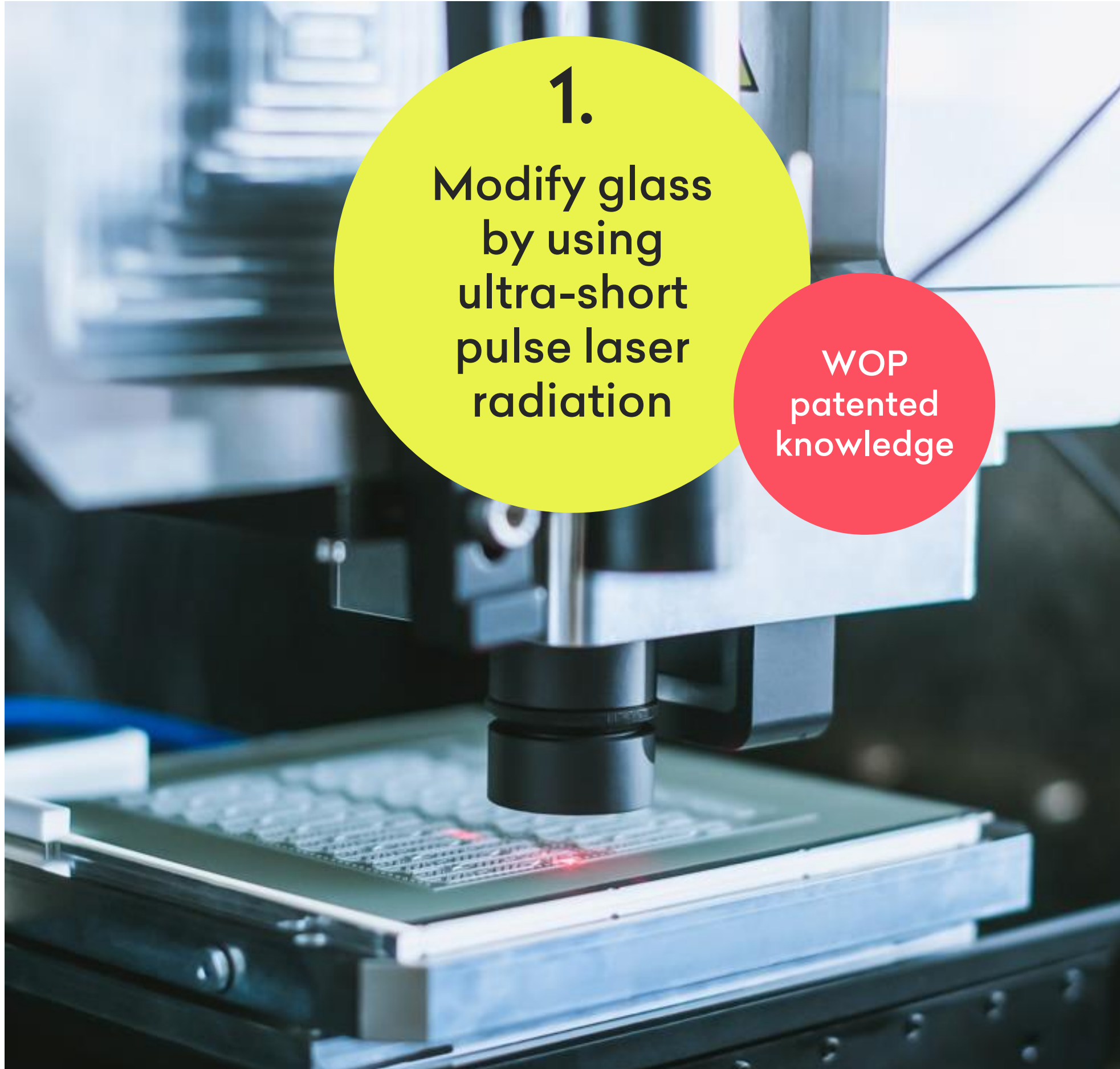
1.

Modify glass
by using
ultra-short
pulse laser
radiation

WOP
patented
knowledge

2.

Remove the
modified
areas using
wet chemical
etching



SLE Allows to Reach Exceptional Properties



SLE technology ensures
zero micro-cracks or chipping

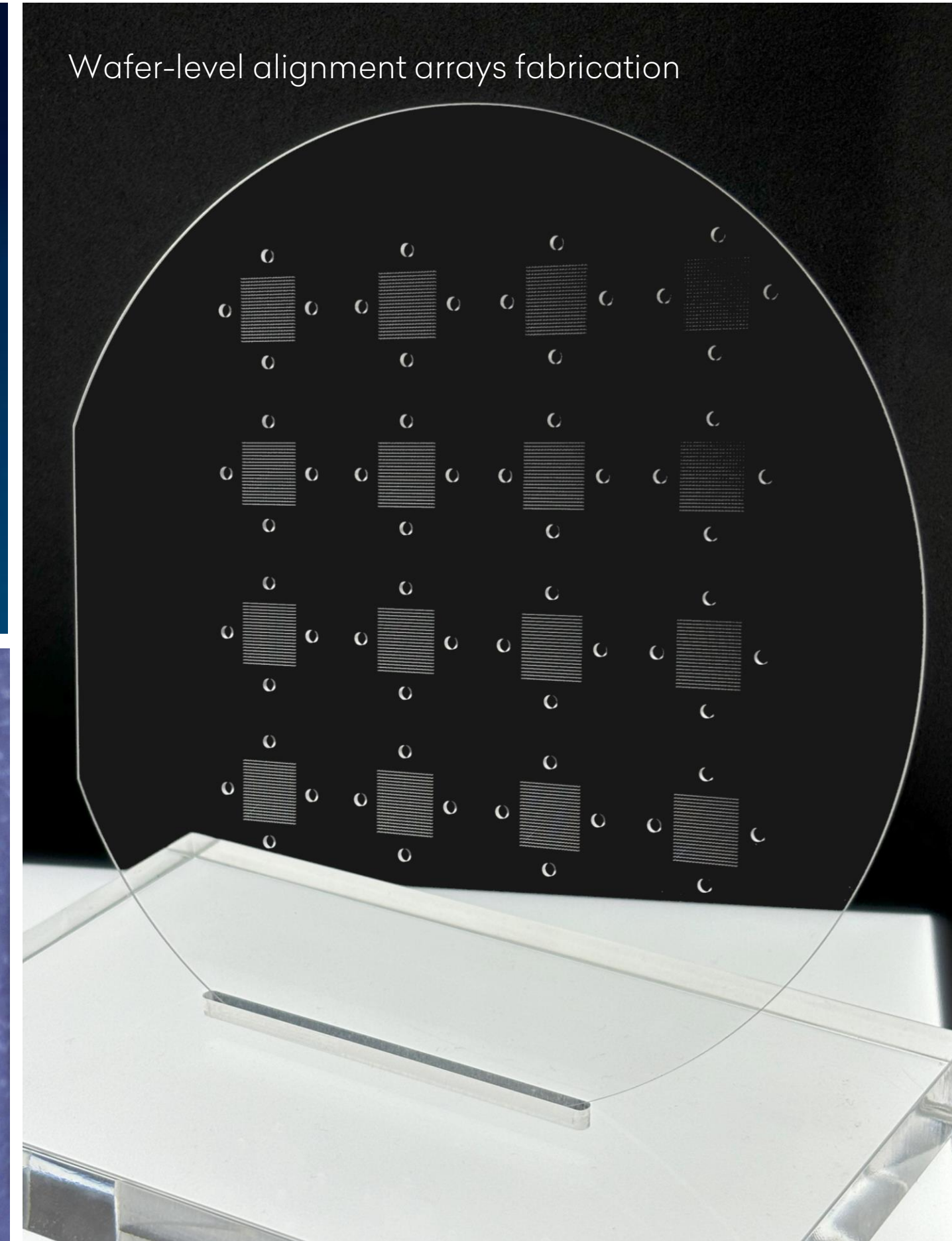
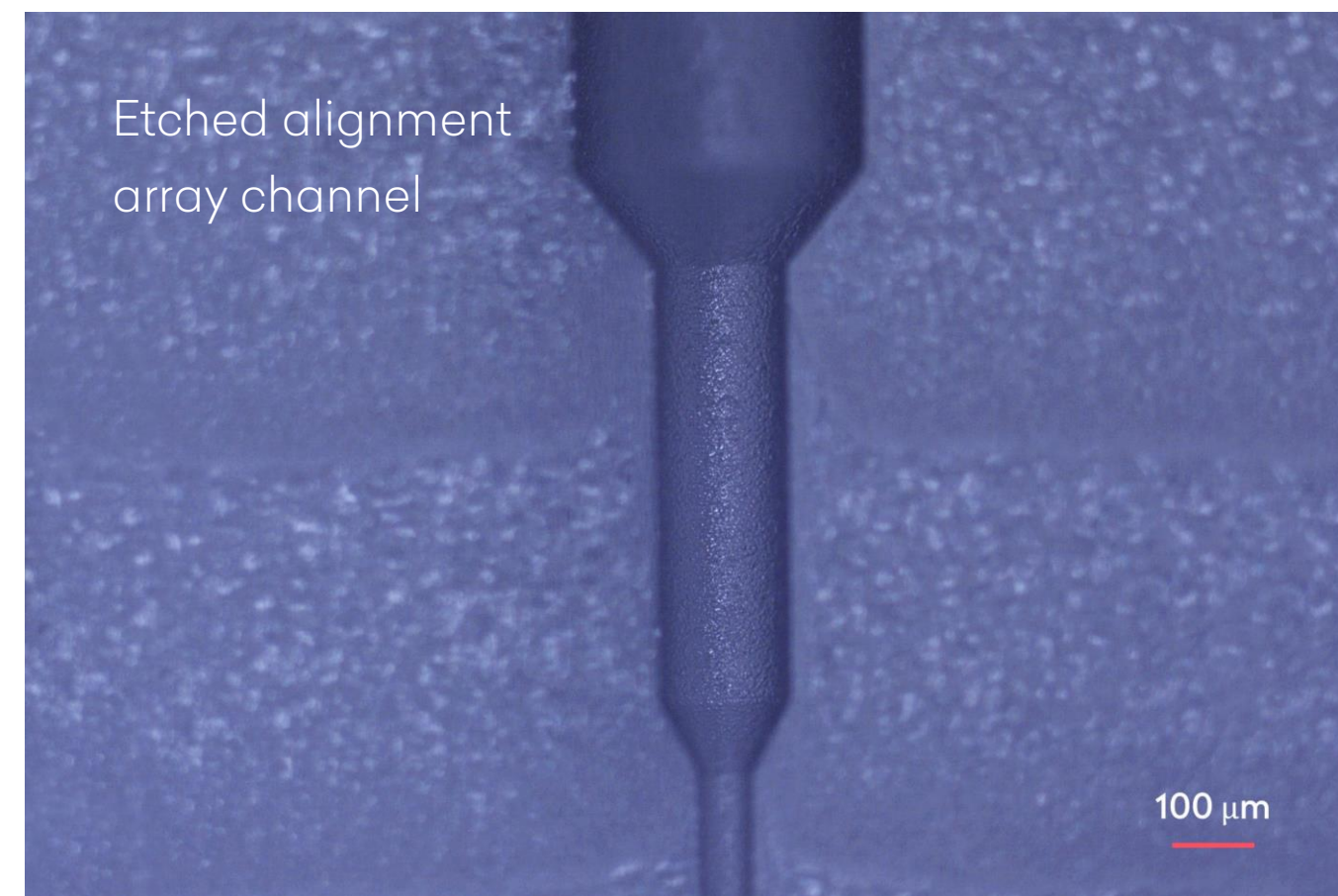
Various shapes:
circular, square, irregular

High aspect ratio
up to 1:100

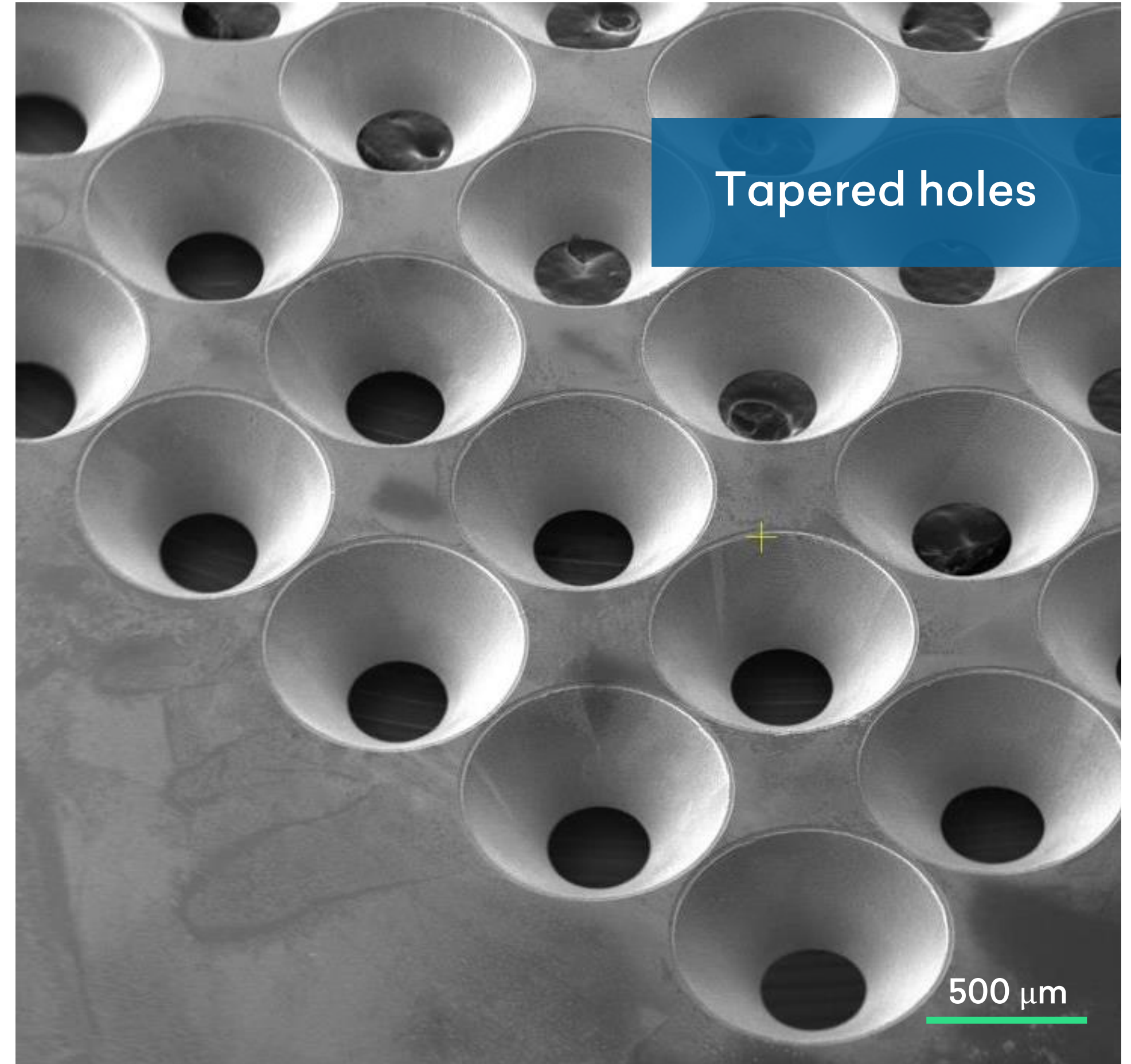
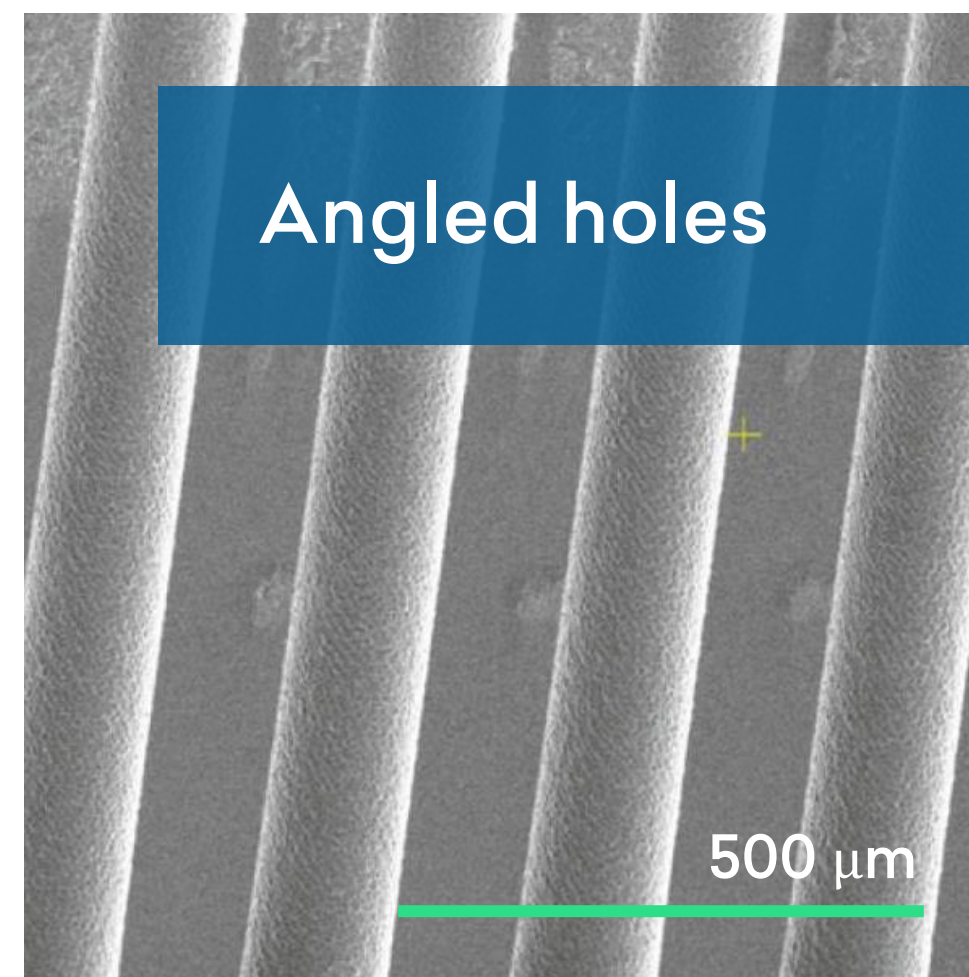
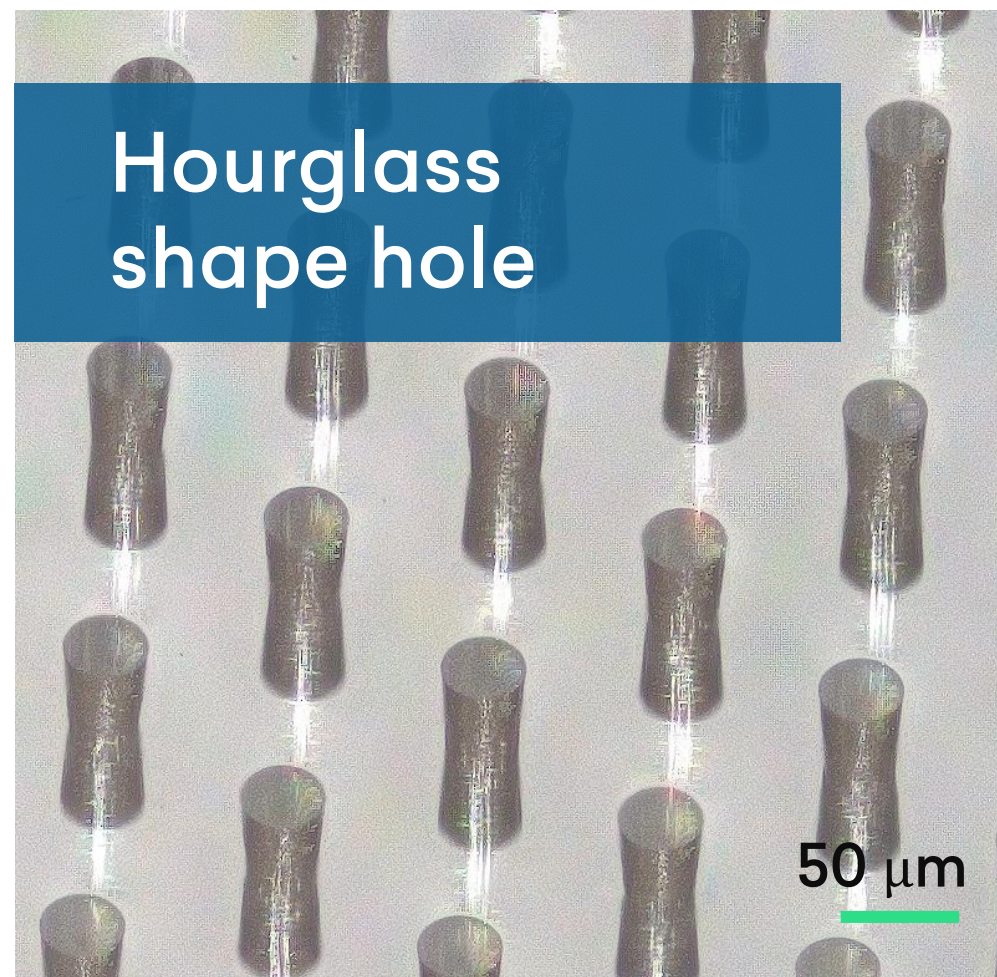
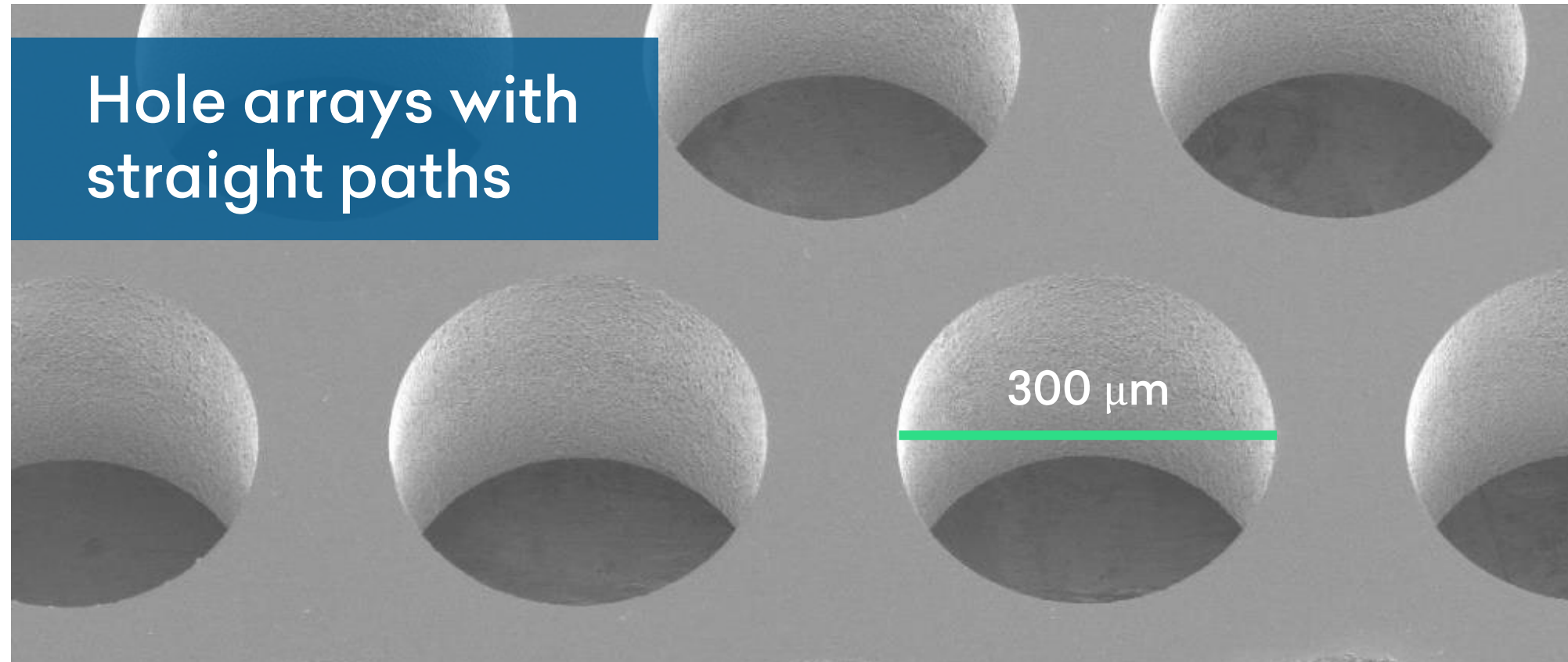
Glass types:
Borofloat 33 and Fused Silica

Wafer level production
up to 200 mm x 200 mm (8")

Thickness:
from 500 μm to 6 mm

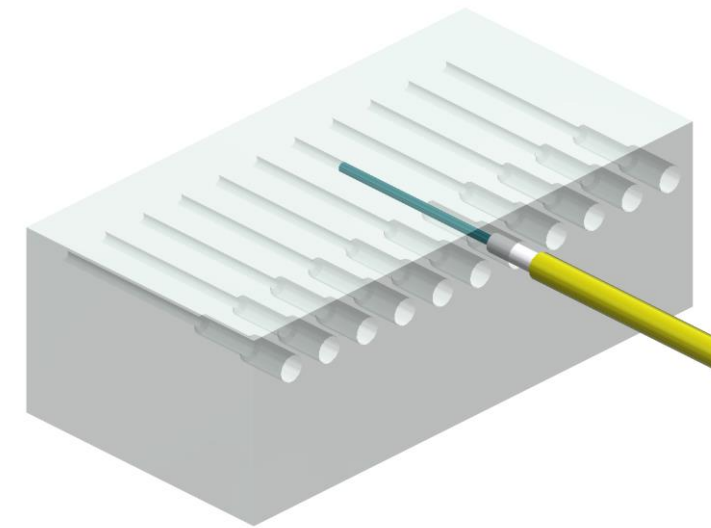


All Kind of Holes in Glass

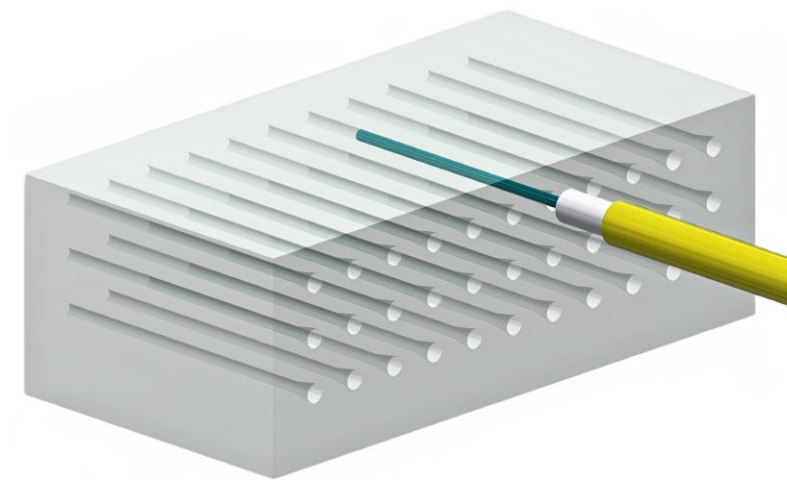


SLE | Perfect Technology For Enhanced 2D Optical Fiber Alignment

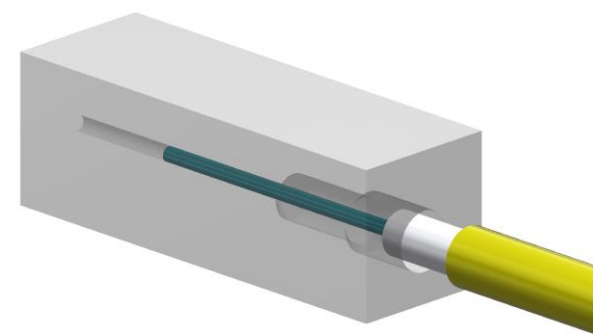
- Designed for:
 - standard SMF fibers, diameter 125/250 μm ,
 - reduced clad fibers 80 μm (not limited)
- Tight tolerances within $\pm 0.25 \mu\text{m}$
- High density, standard 0,25 mm pitch
- Circularity $< 1 \mu\text{m}$ diameter
- Diameter tolerance $\pm 0,5 \mu\text{m}$
- Pitch tolerance $\pm 0,5 \mu\text{m}$
- Positional accuracy $< 0,5 \mu\text{m}$
- Straight, flared, or with a cone for easier insertion
- Straight or angled holes



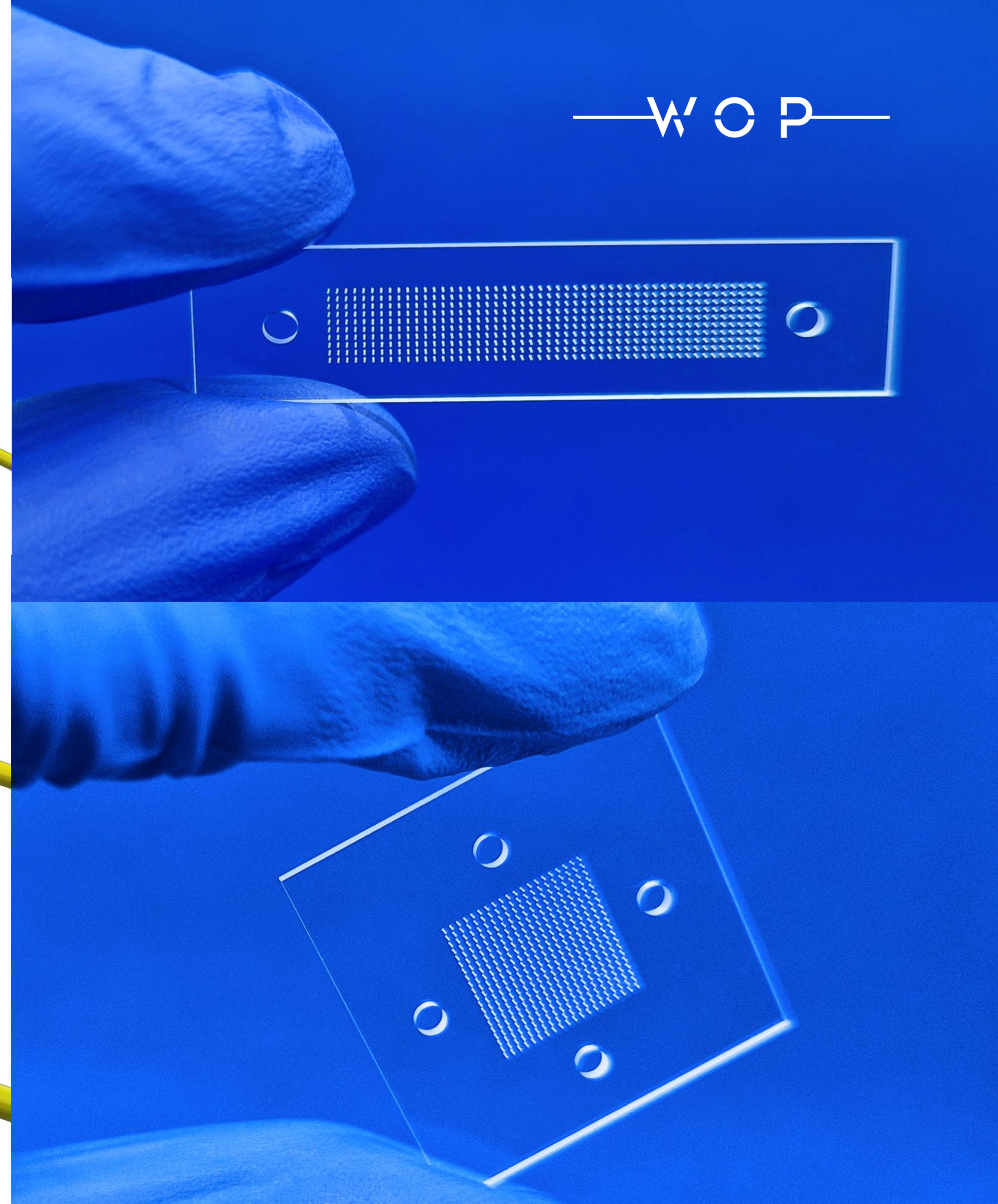
1D Alignment array with SMF fiber



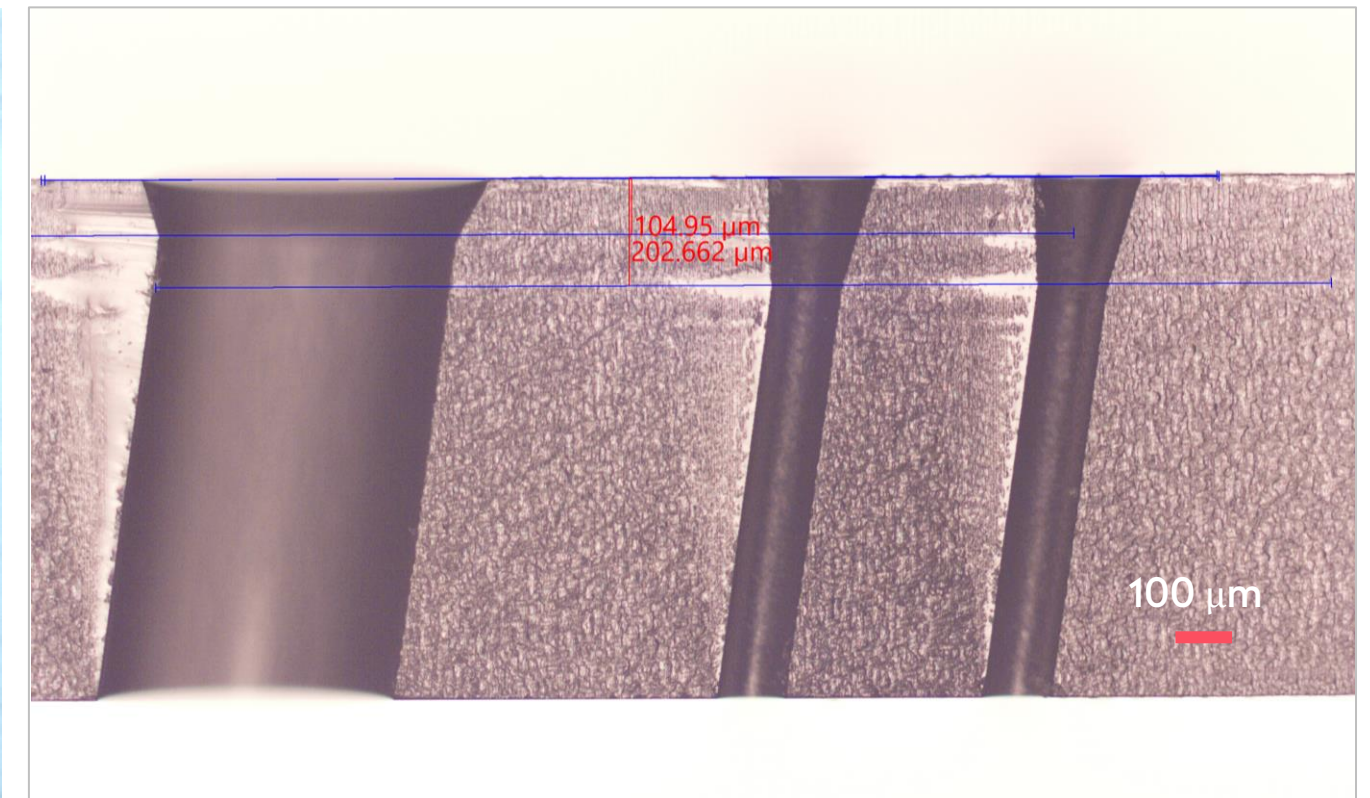
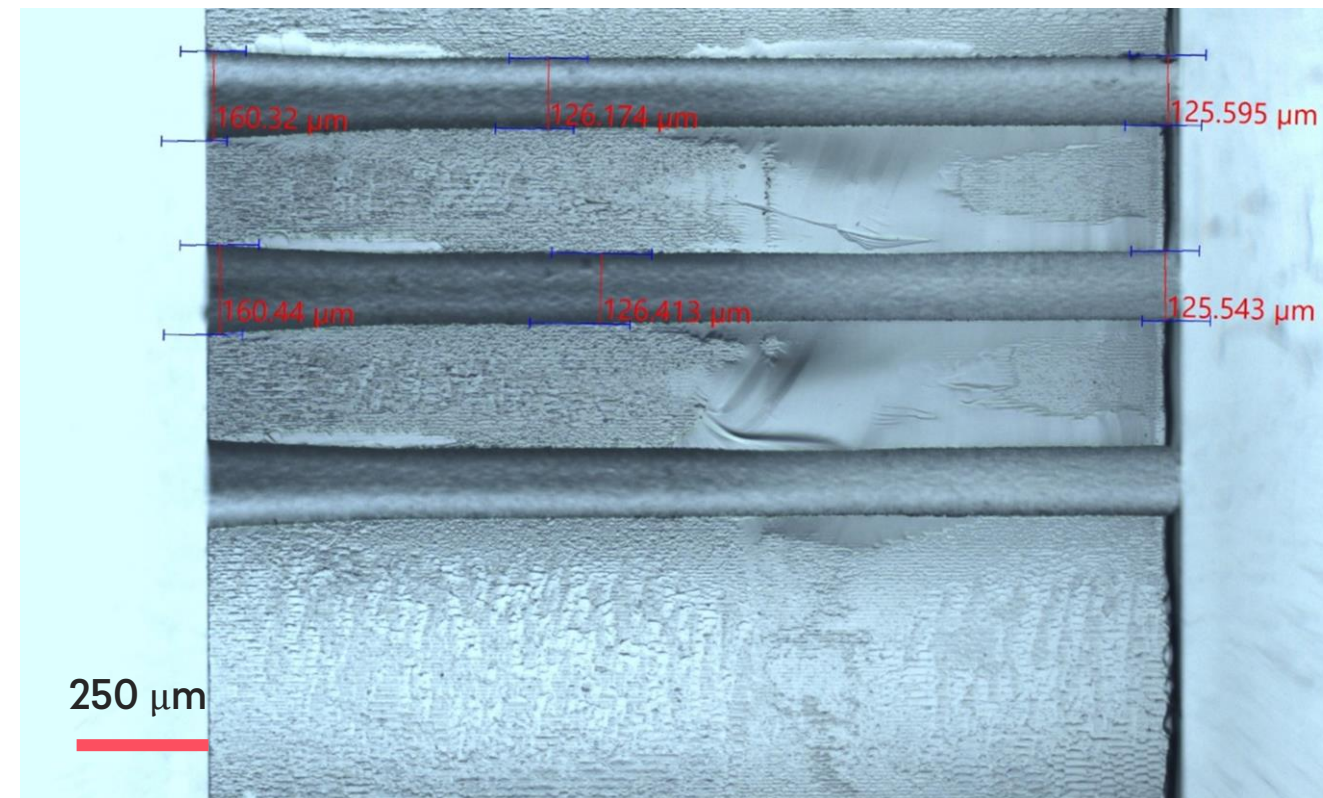
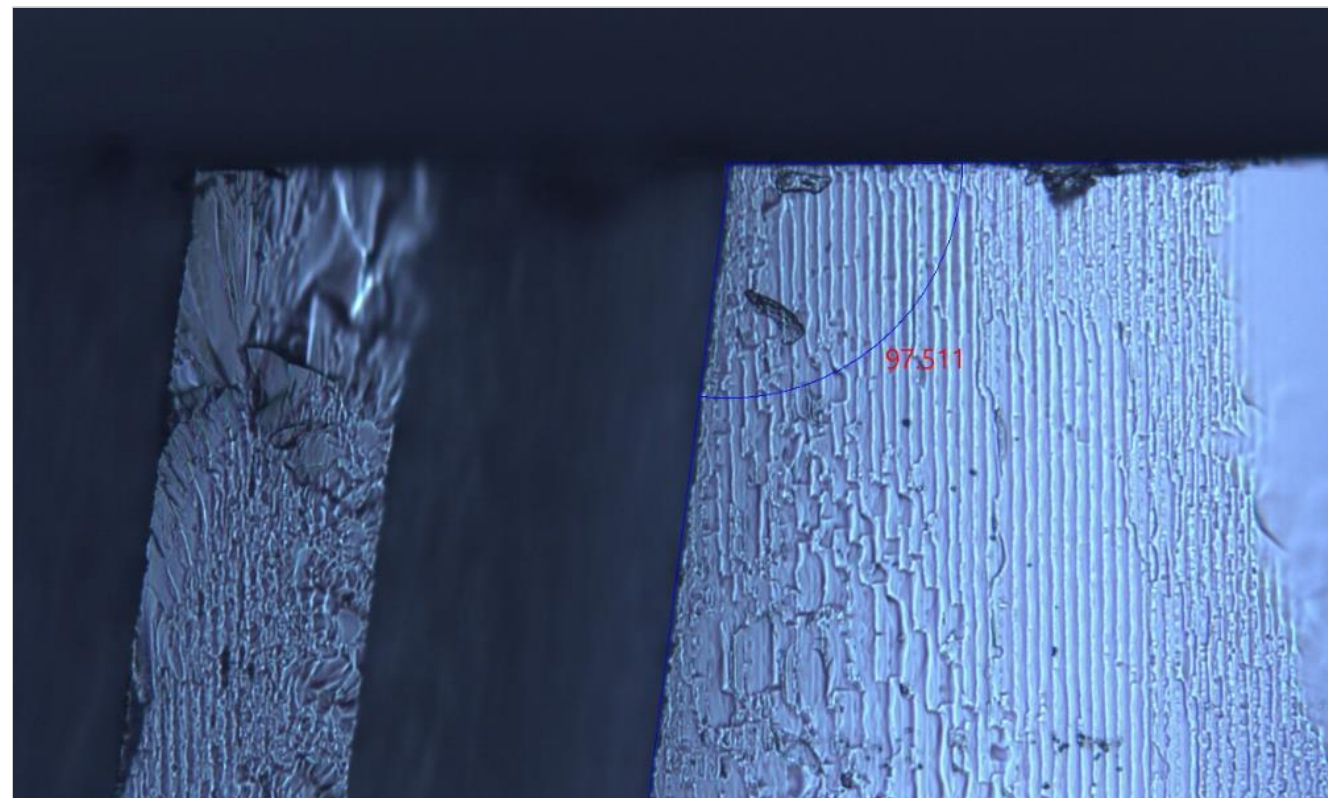
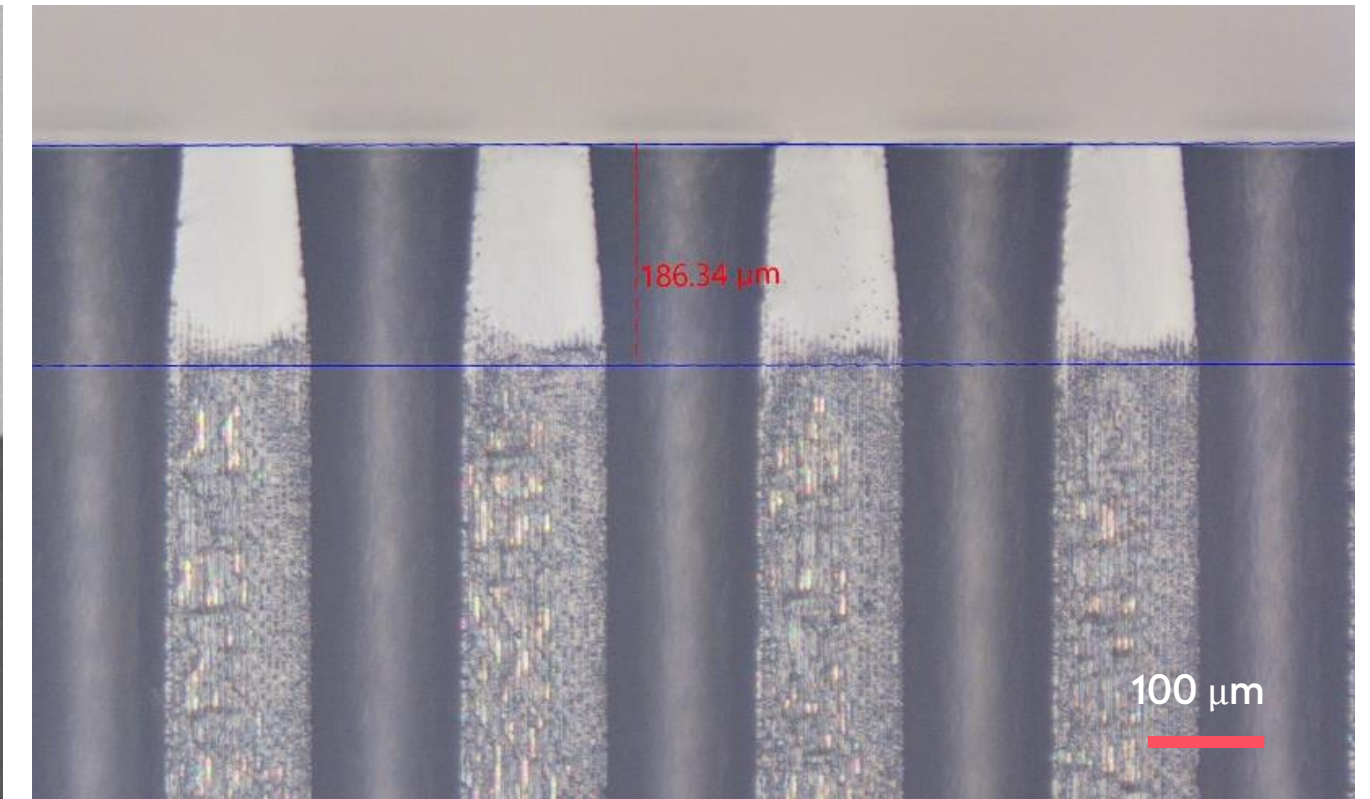
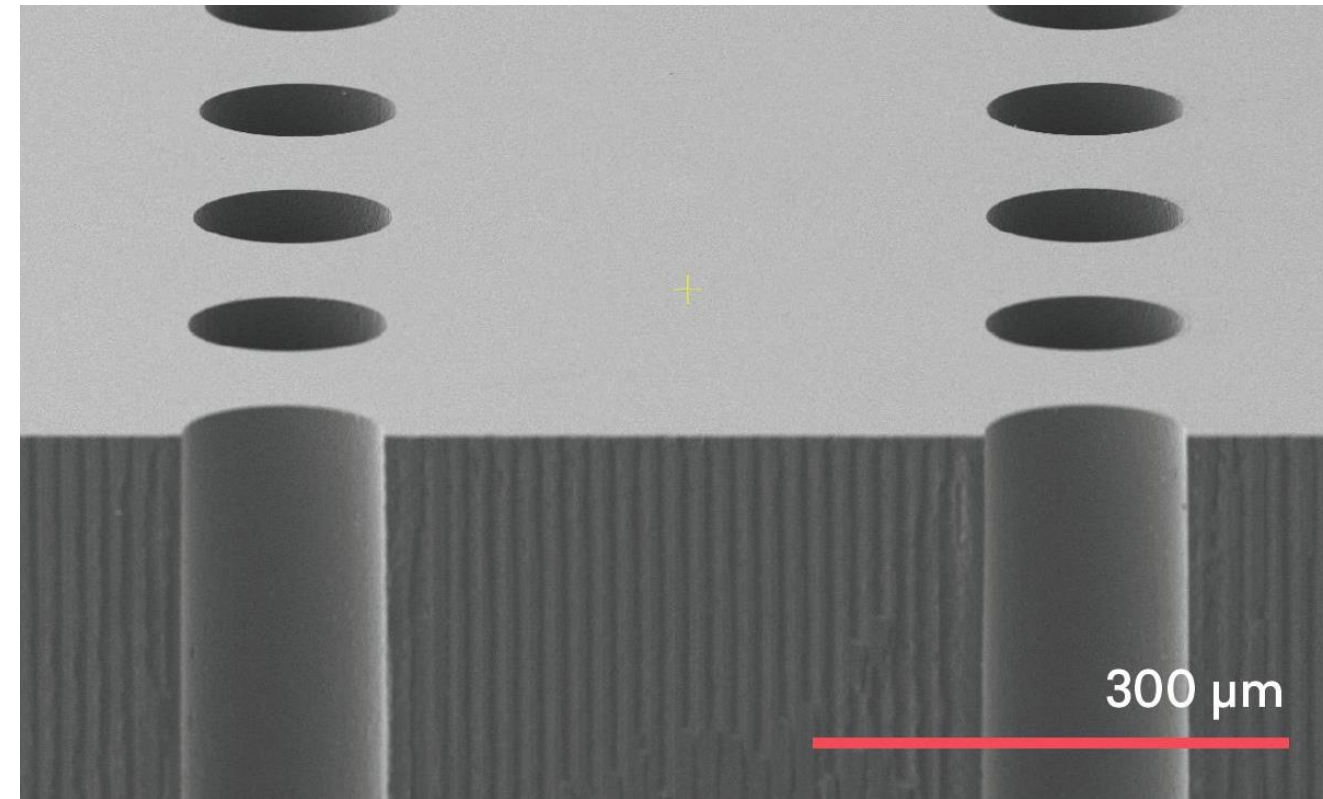
2D Alignment array with SMF fiber



One hole example with SMF fiber



All Guide Shapes

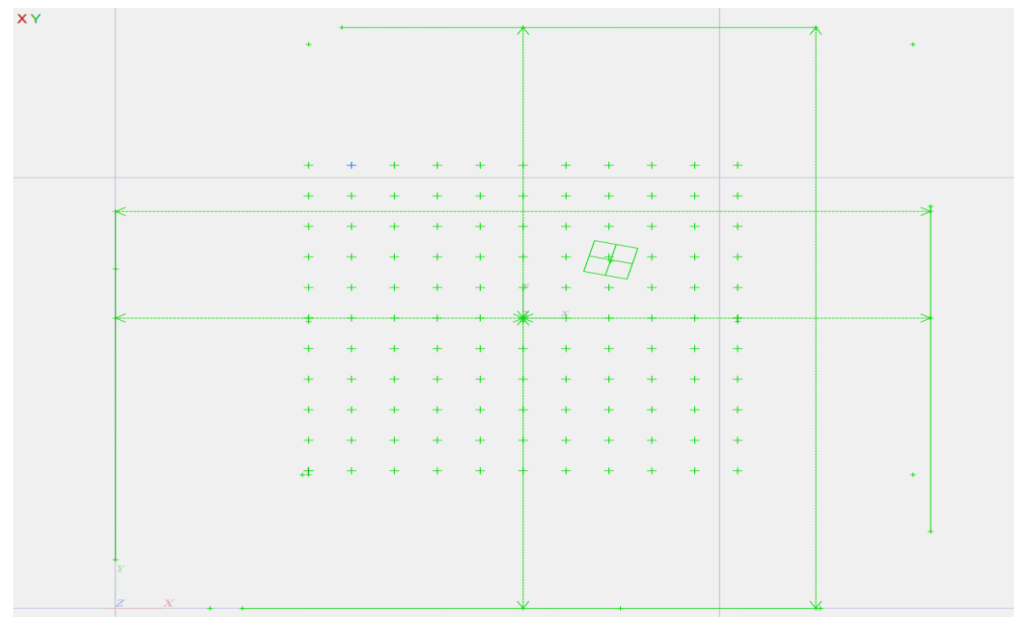


Sub-micron control of 2D Optical Fiber Alignment

2D array 11x11 (Hole diameter = $125.5 \pm 0.5 \mu\text{m}$)

FIBER CORE/HOLE POSITION ERROR

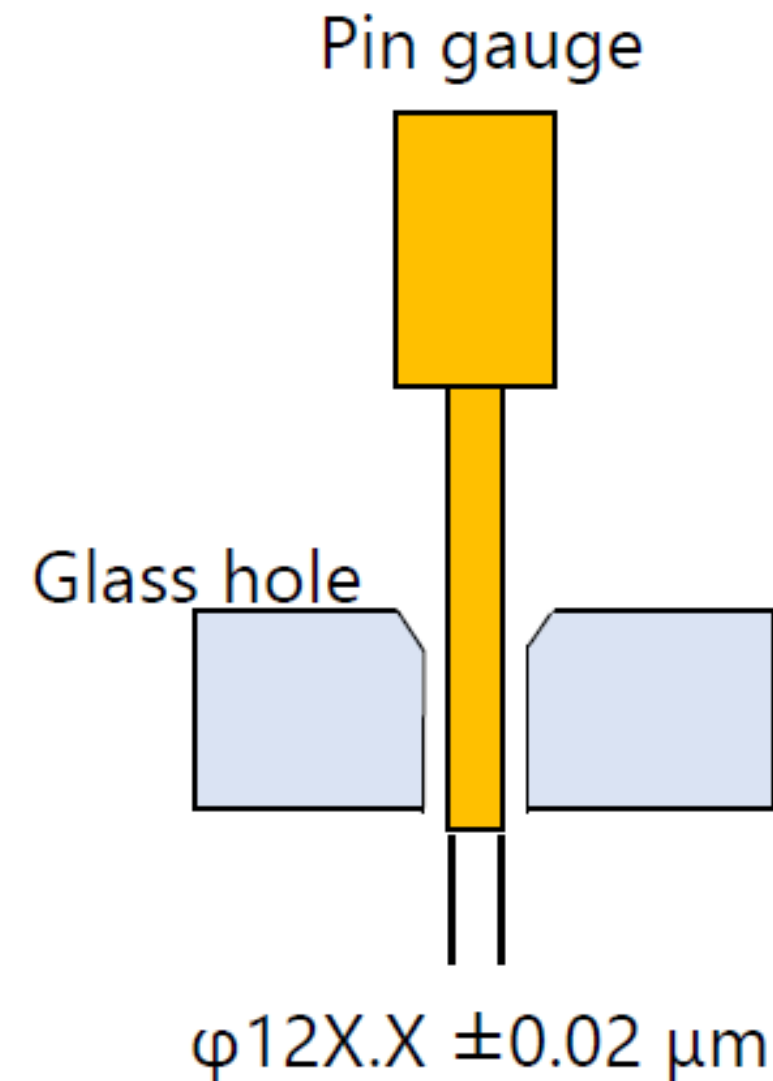
Automated measurement tool Nikon Nexiv VMZ-S for X,Y, D, TRUE POSITION



Hole Nr.		Nom., μm	UpperTol., μm	LowerTol., μm	Sample Nr. 1 Measured, μm	Sample Nr. 5 Measured, μm
1-1	X	0	0,5	-0,5	-0.0	0.0
1-1	Y	0	0,5	-0,5	-0.0	-0.0
1-1	D	125,5	0,5	-0,5	125.8	125.9
1-8	X	1750	0,5	-0,5	1750.0	1750.0
1-8	Y	0	0,5	-0,5	-0.3	-0.2
1-8	D	125,5	0,5	-0,5	125.9	126.1
1-16	X	3750	0,5	-0,5	3749.8	3749.9
1-16	Y	0	0,5	-0,5	-0.4	-0.1
1-16	D	125,5	0,5	-0,5	125.8	126.0
1-24	X	5750	0,5	-0,5	5749.6	5750.1
1-24	Y	0	0,5	-0,5	-0.4	-0.0
1-24	D	125,5	0,5	-0,5	126.0	126.1
1-32	X	7750	0,5	-0,5	7749,6	7749.9
1-32	Y	0	0,5	-0,5	0.0	-0.0
1-32	D	125,5	0,5	-0,5	125.9	126.0
8-1	X	0	0,5	-0,5	-0.4	0.1
8-1	Y	-1750	0,5	-0,5	-1749.9	-1750.0
8-1	D	125,5	0,5	-0,5	125.8	125.9
8-8	X	1750	0,5	-0,5	1749,6	1749.8
8-8	Y	-1750	0,5	-0,5	-1749.8	-1750.2
8-8	D	125,5	0,5	-0,5	125.8	125.7

HOLE DIAMETER CONTROL

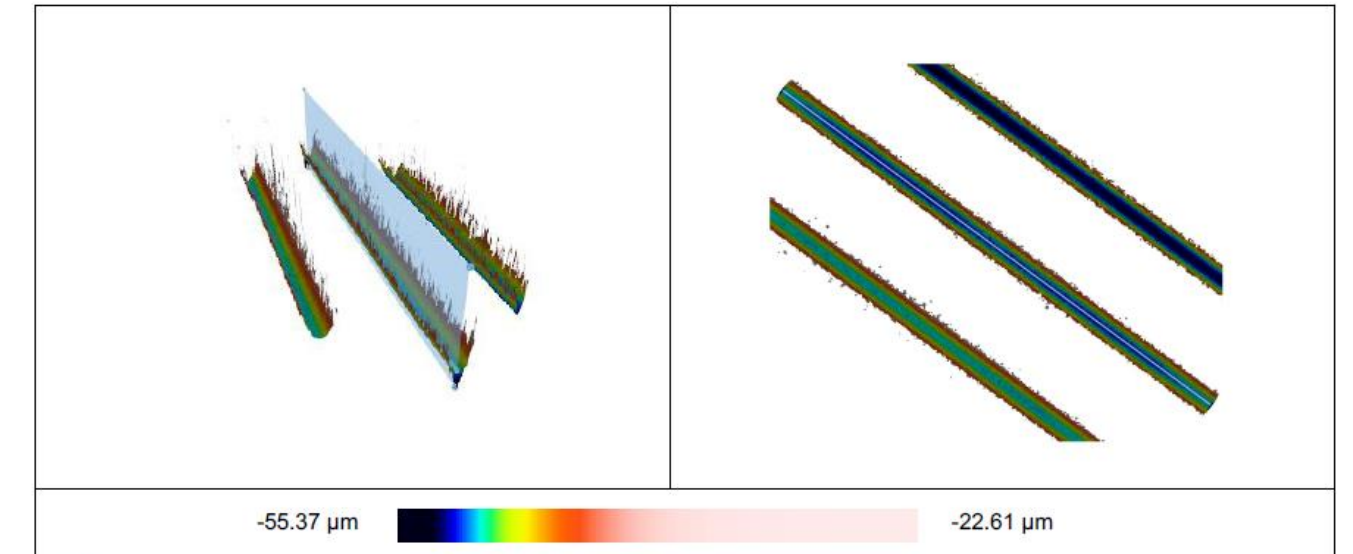
Guiding section verification by using mechanical pins and fibers itself



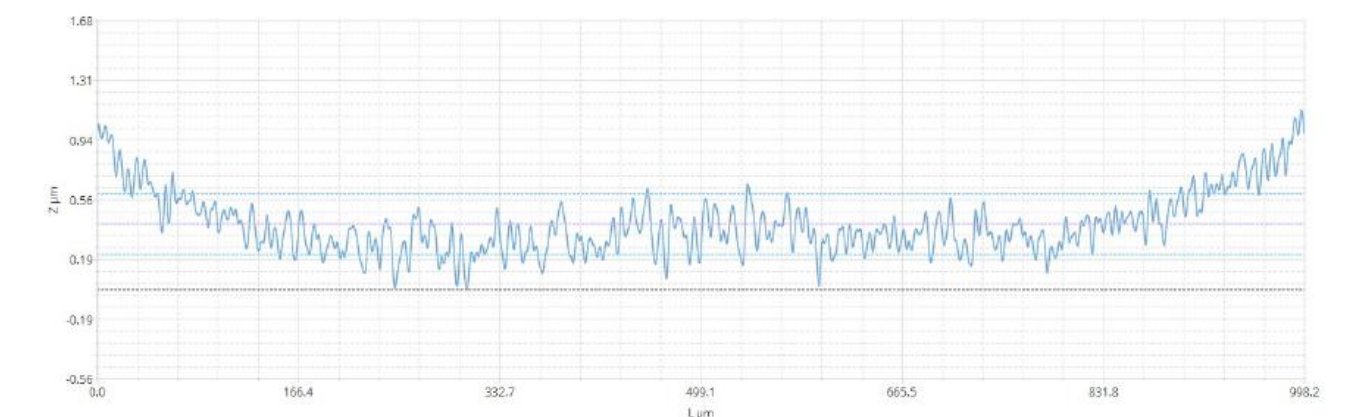
ROUGHNESS INSIDE THE HOLE

3D Optical Profiler Sensofar Neox

Visualization

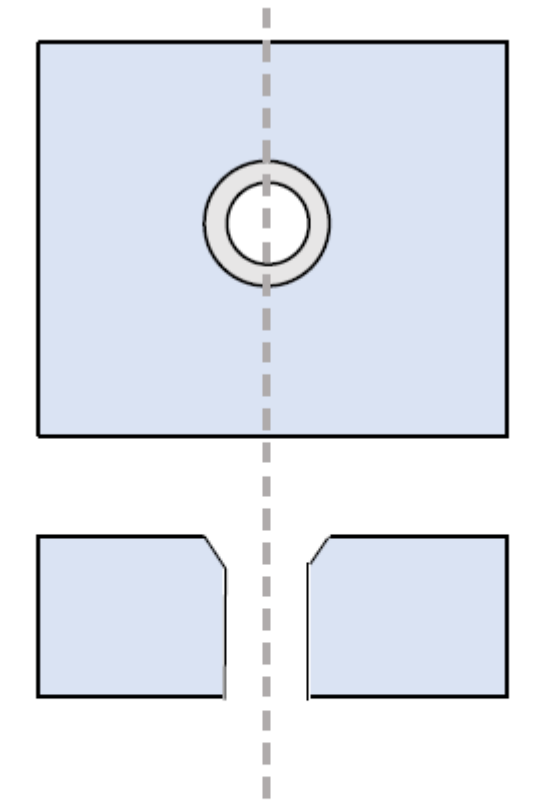
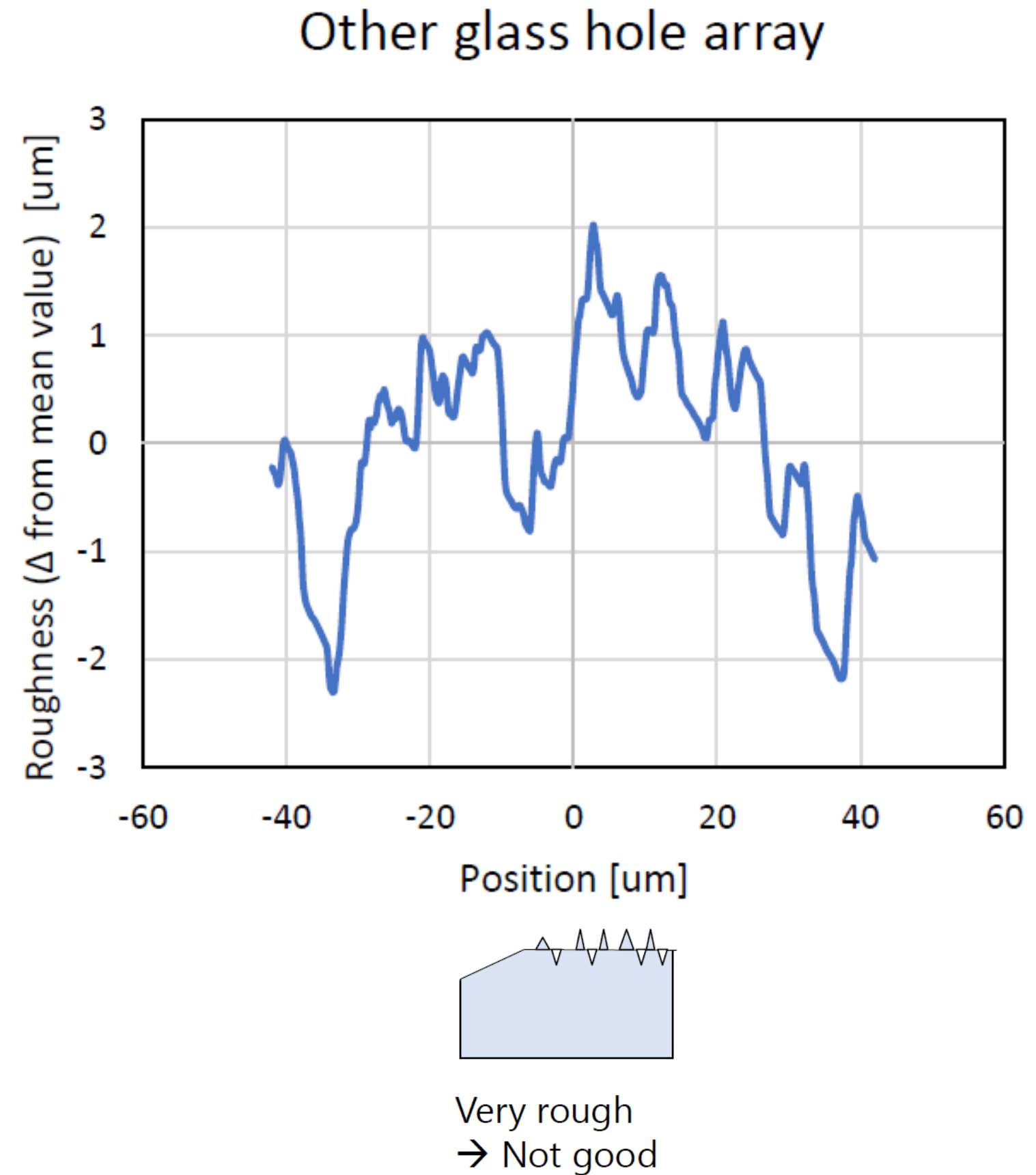
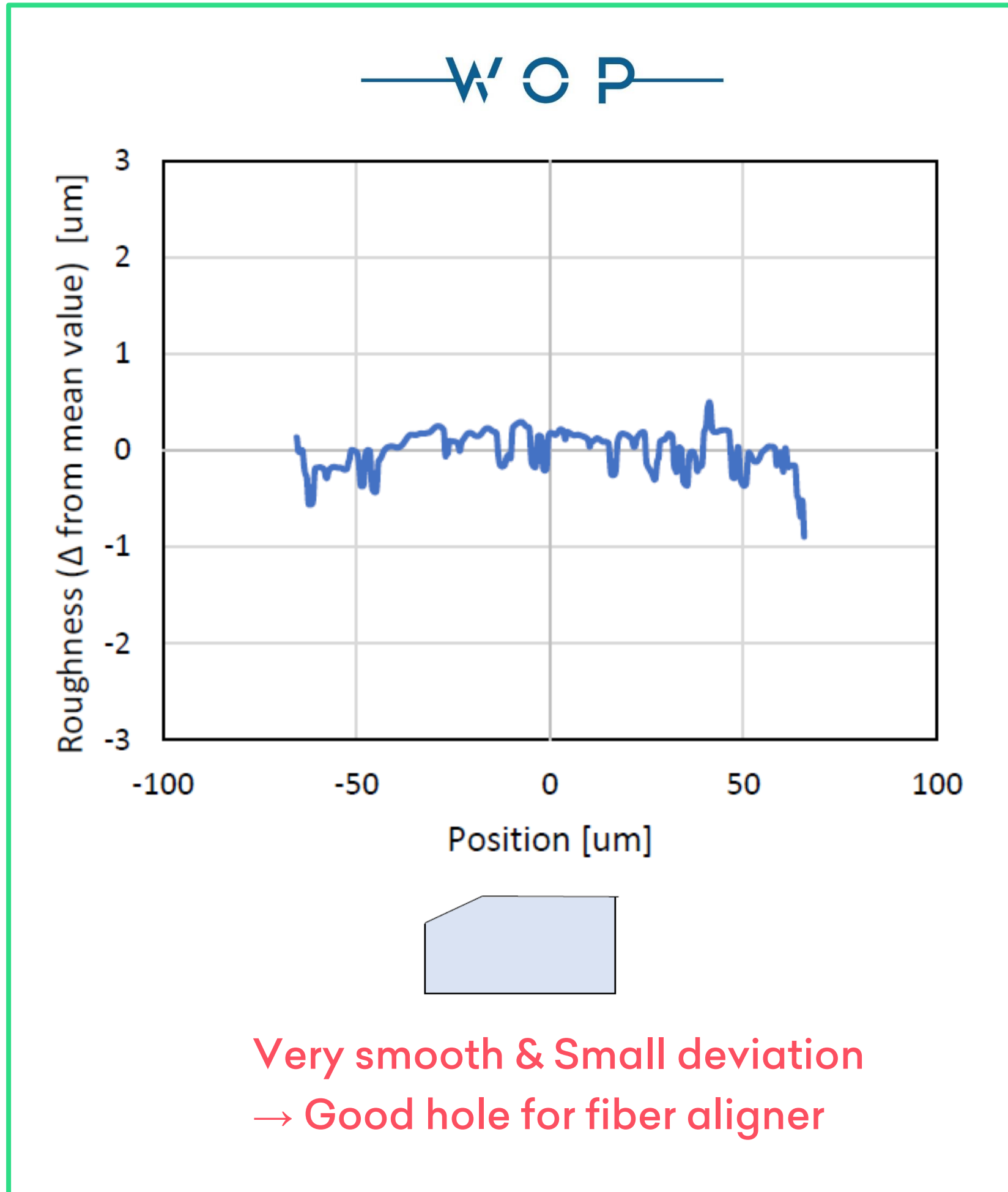


Profile



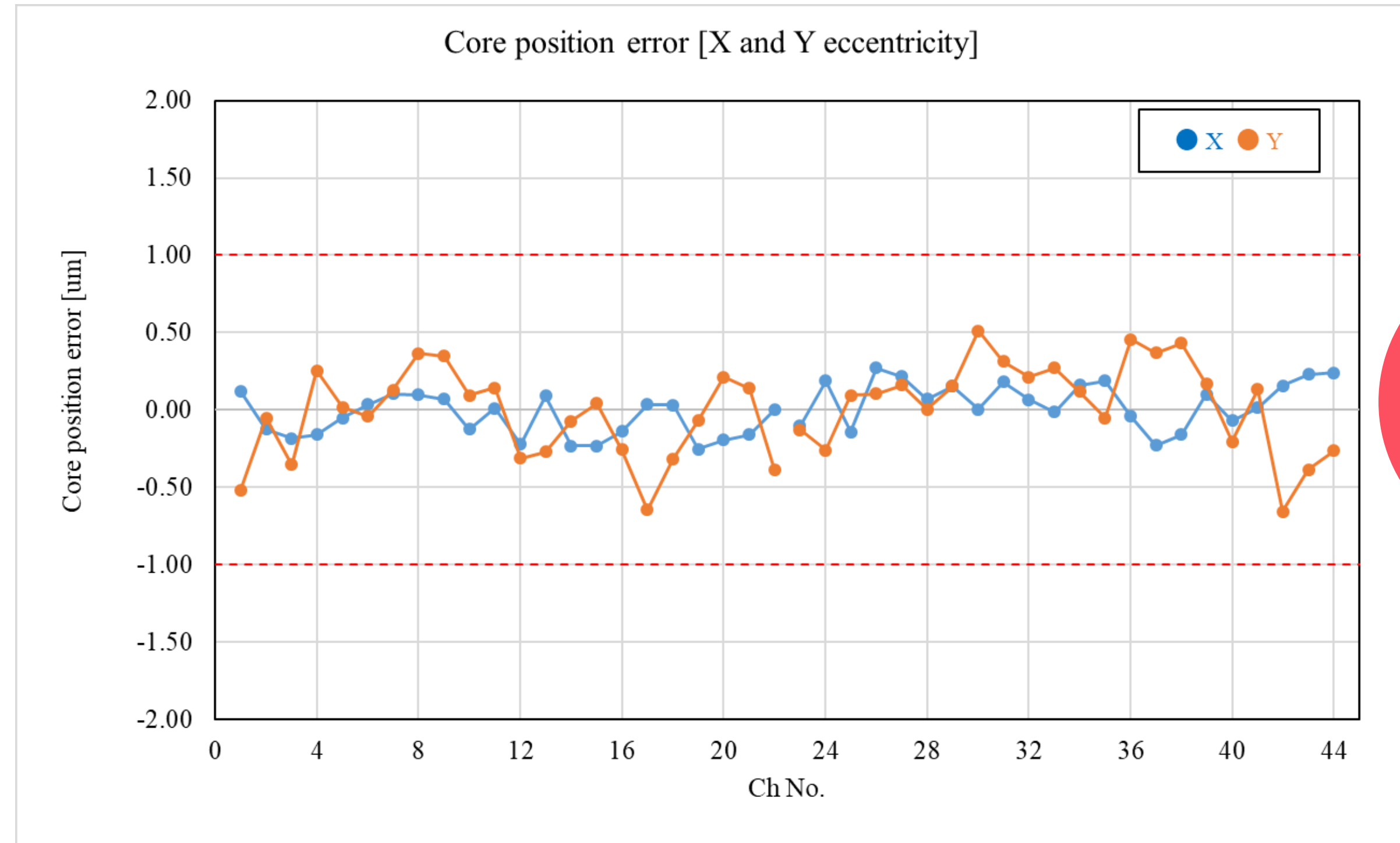
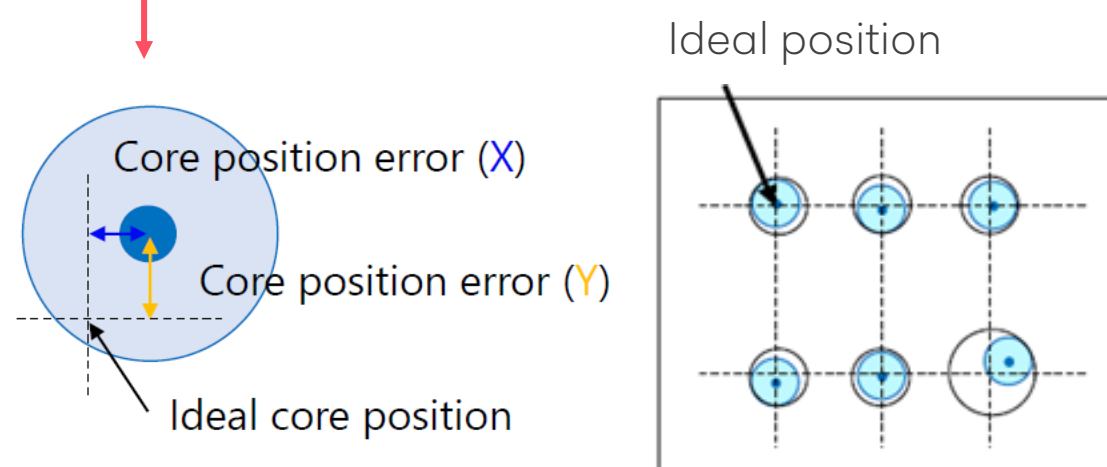
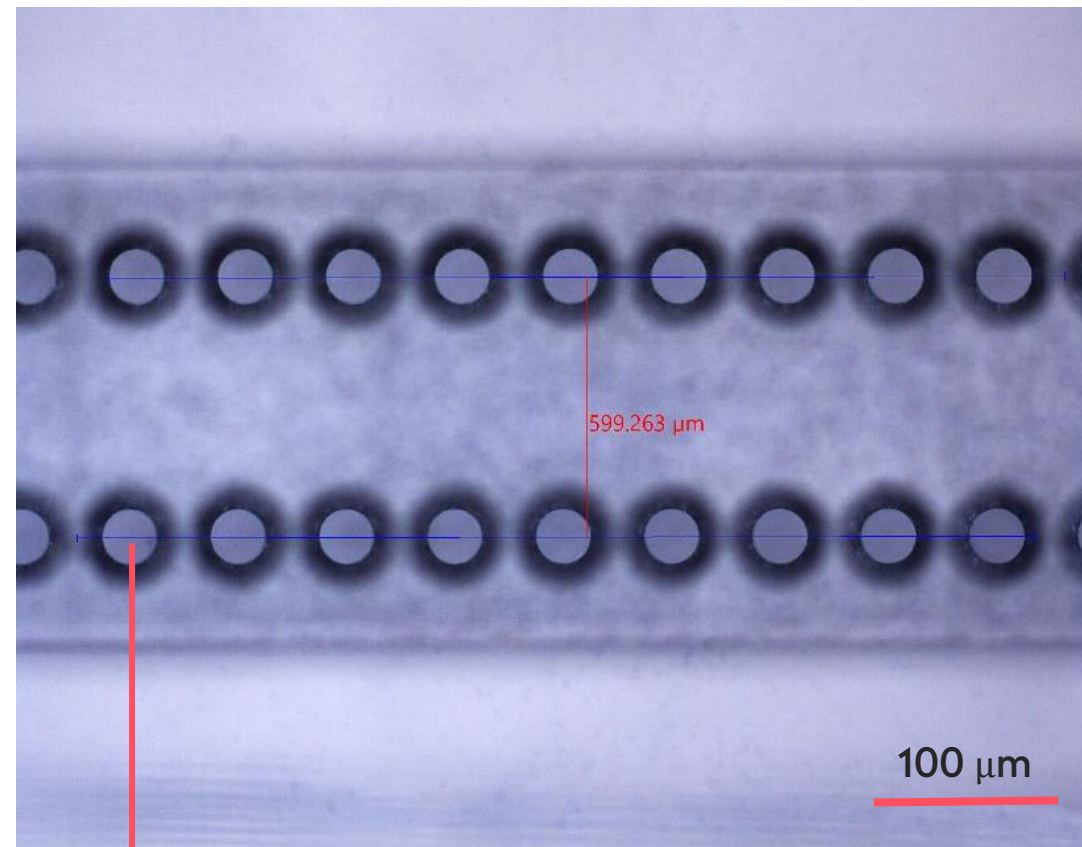
High-end metrology: Scanning electron microscope | SEM, Sensofar Neox profilometer, Nikon Nexiv VMZ-S

Evaluation 1: Hole Roughness



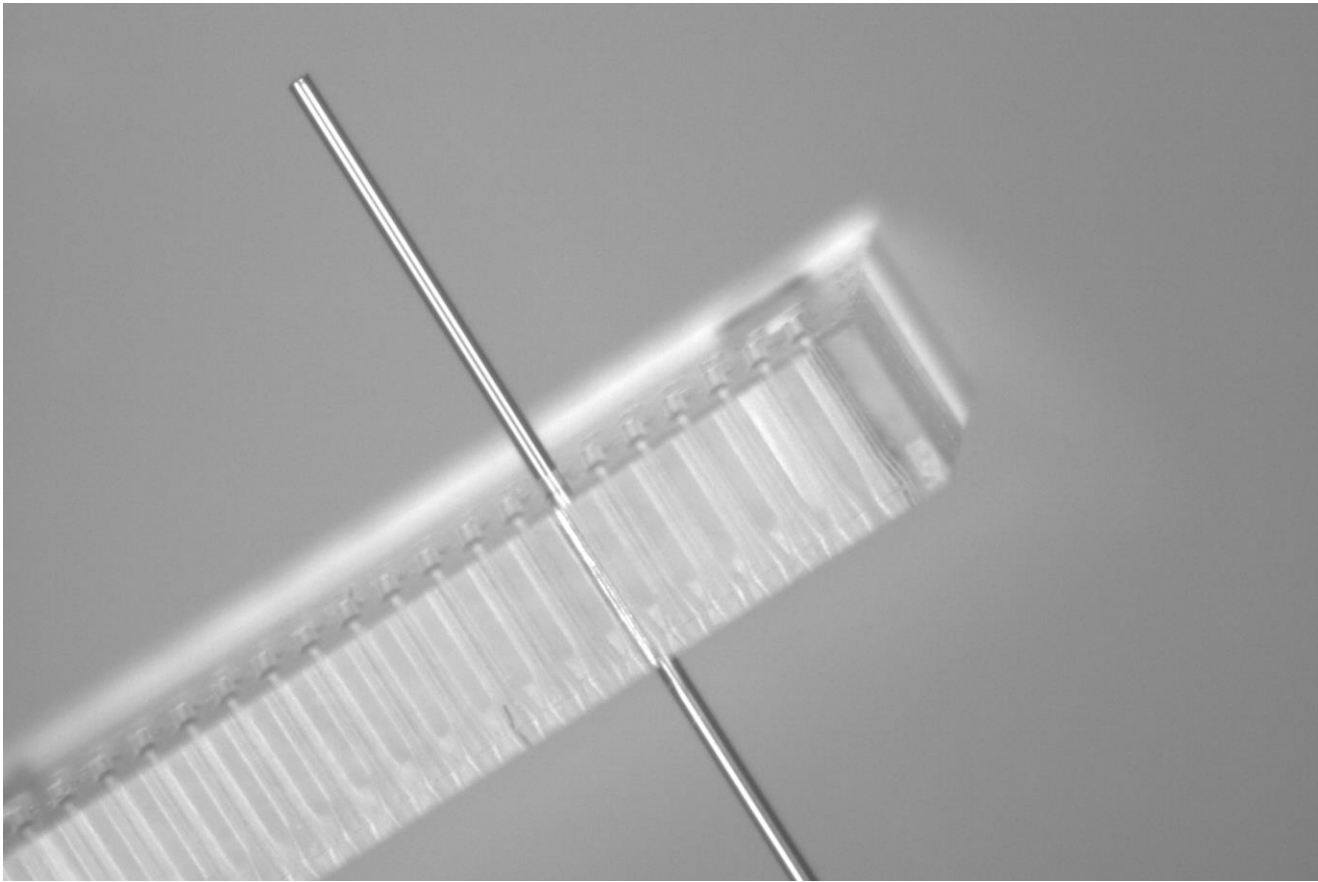
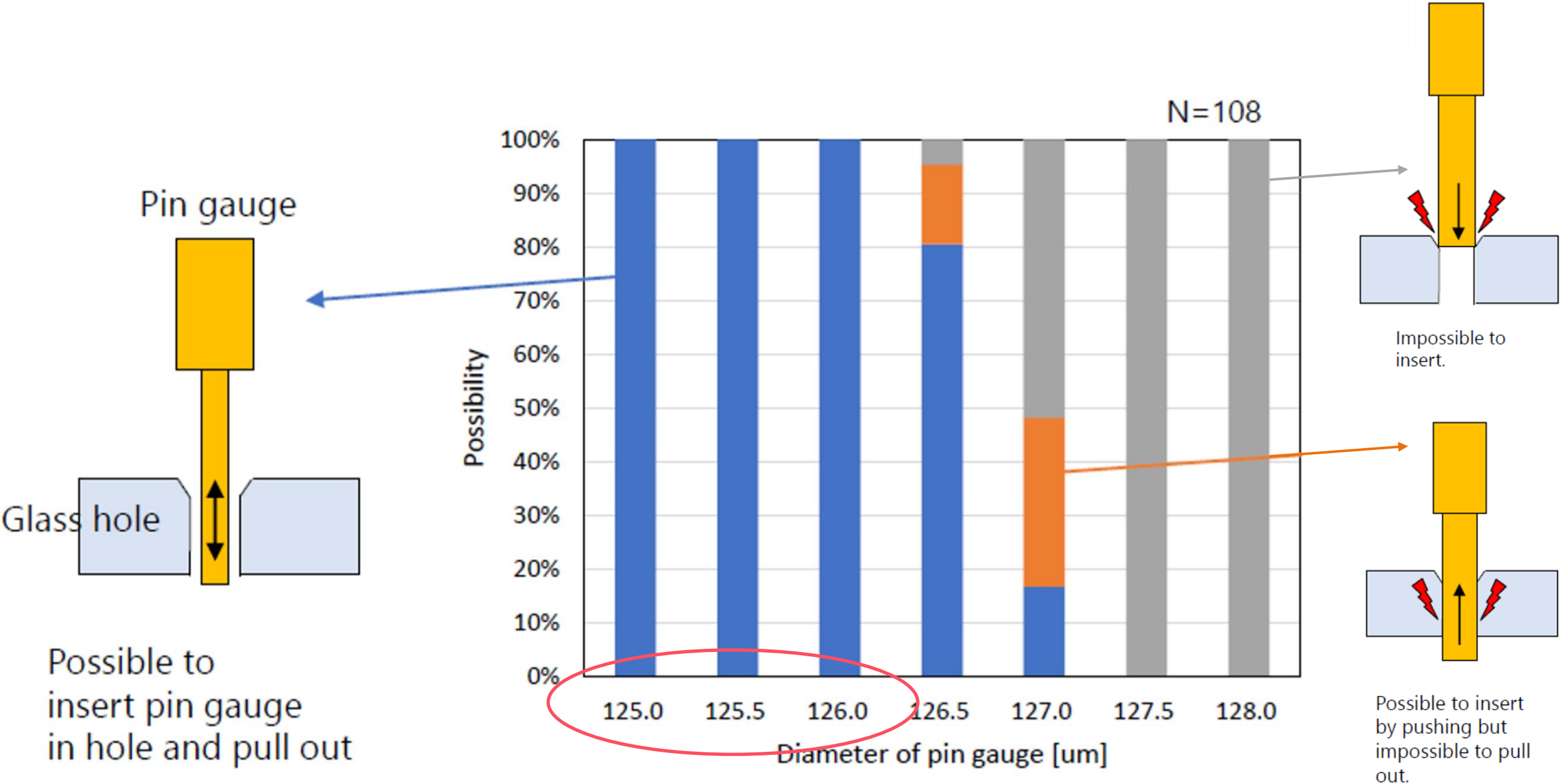
Cut the glass hole array and measured roughness of inside hole.

Evaluation 2: Fiber Core Position



Low core position error is confirmed.
Low coupling loss is expected.

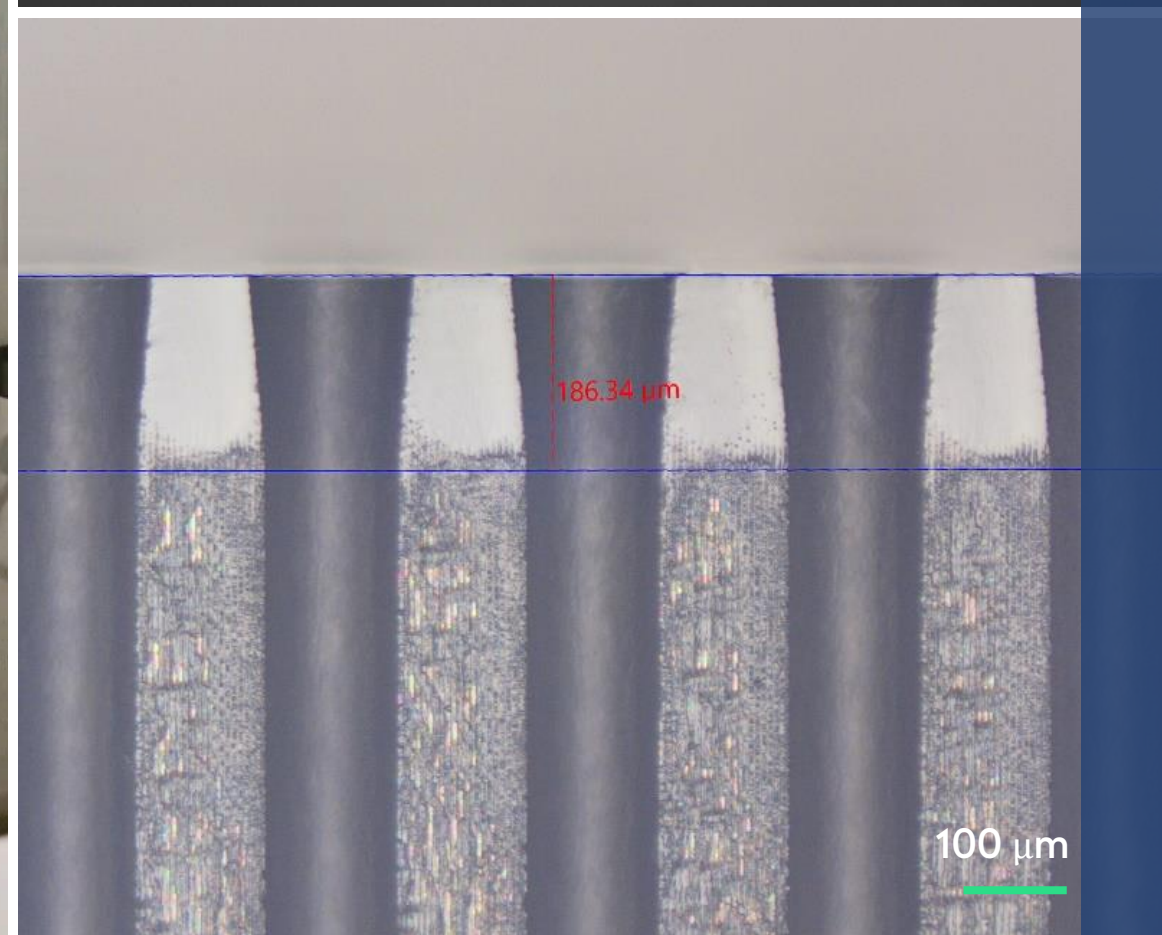
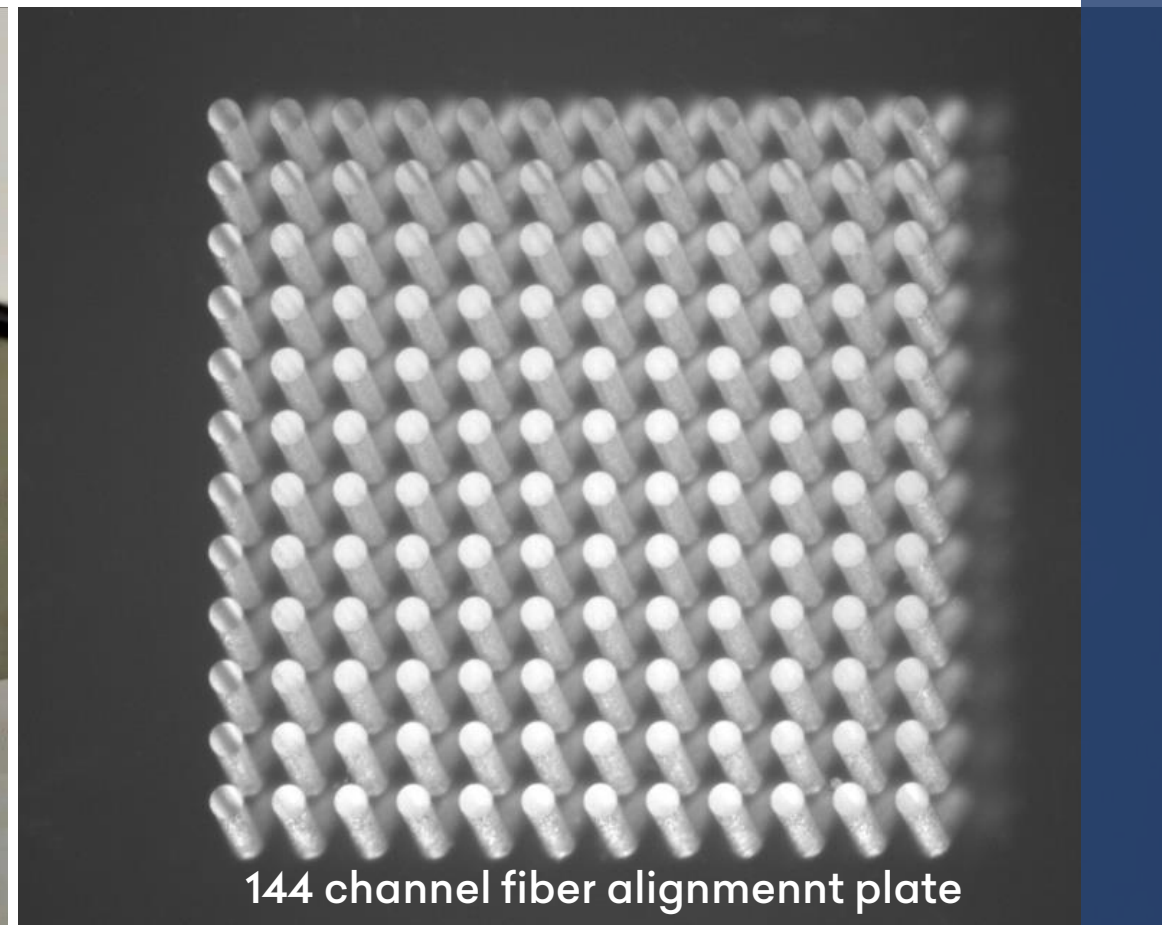
Evaluation 3: Perfect Hole Diameter



Specification of hole diameter is 126 +1/ -0 μm

Perfect Fiber Arrays

Wafer-level 2D
fiber alignment
arrays fabrication!



- High density | standard 0,25 mm pitch
- High core position accuracy | Average core positioning error $\pm 0.5 \mu\text{m}$
- Tight tolerances within $\pm 0.25 \mu\text{m}$
- Heat resistance
- CTE matching to Silicon
- Low coupling losses
- Ultrafast direct laser writing | suitable for high-scale production





Thank you &
let's connect!



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